

# TWEPP-23

Topical Workshop on Electronics for Particle Physics  
Geremeas, Sardinia, Italy, 2 – 6 October 2023

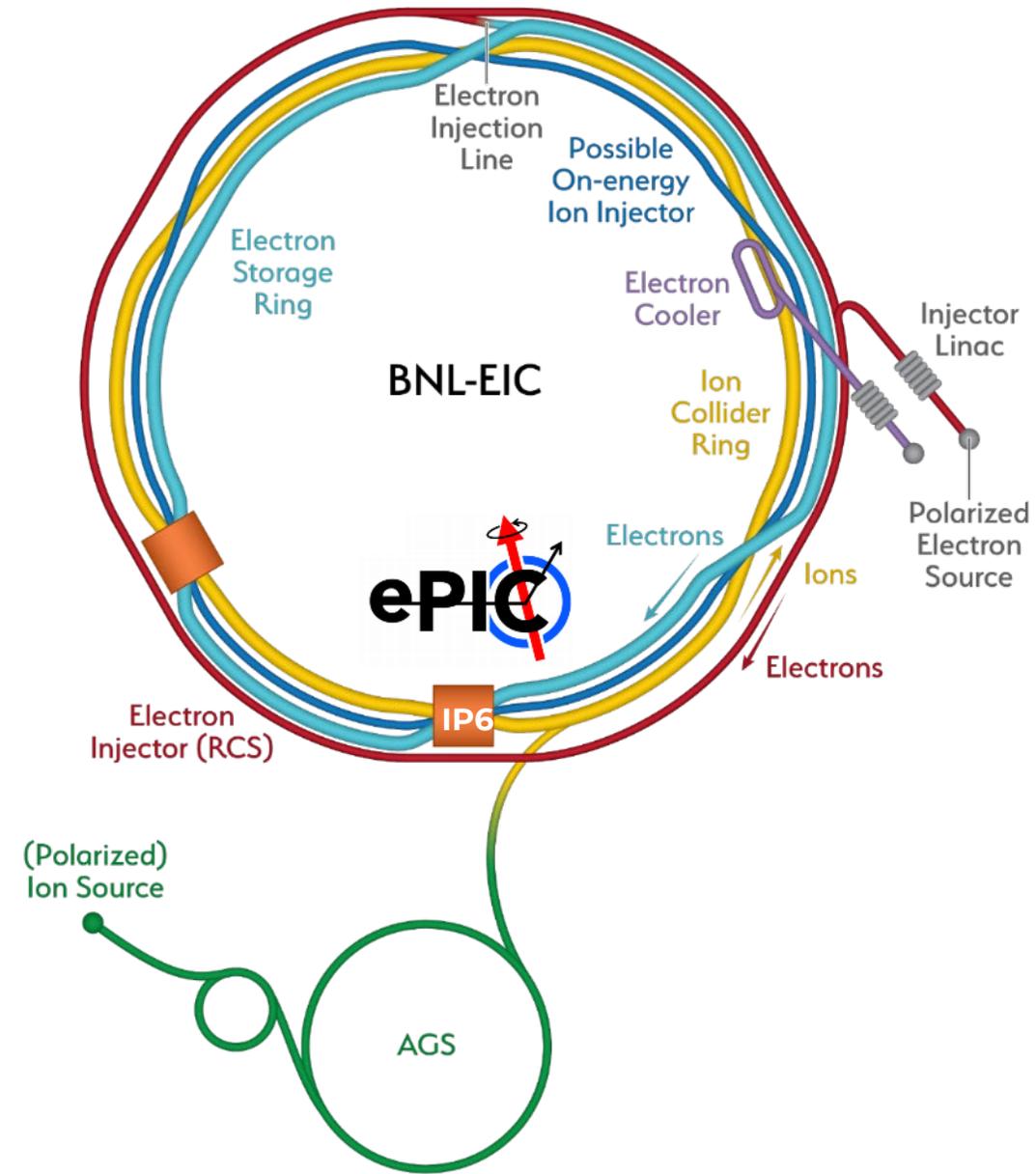
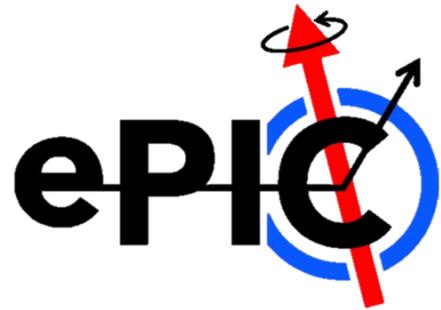
A readout system based on SiPM  
for the dRICH detector at the EIC

TWEPP 2023 - Oct 1–6, 2023 Geremeas, Sardinia, Italy  
INFN BOLOGNA Luigi Rignanese rignanes@bo.infn.it



# Outline

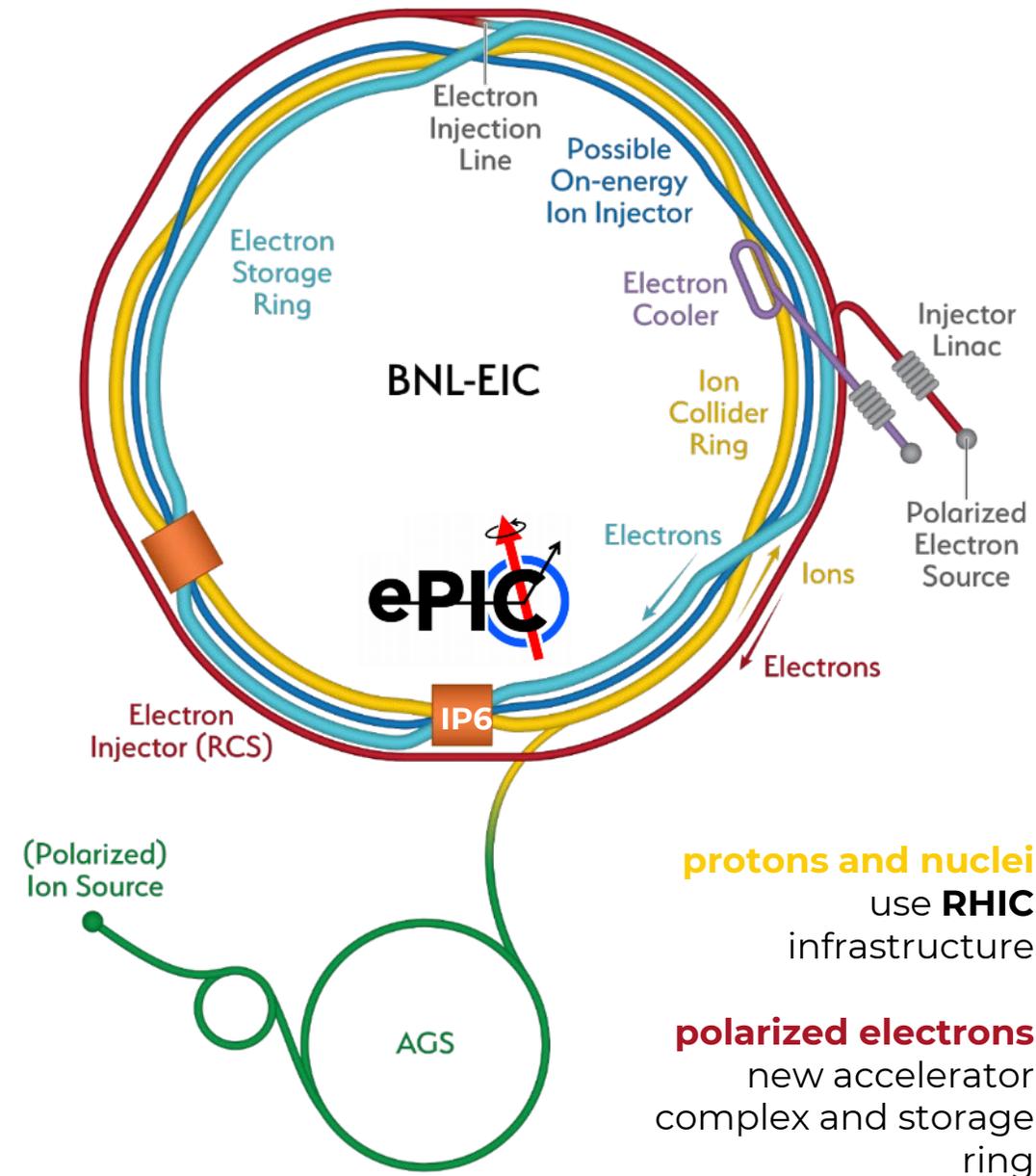
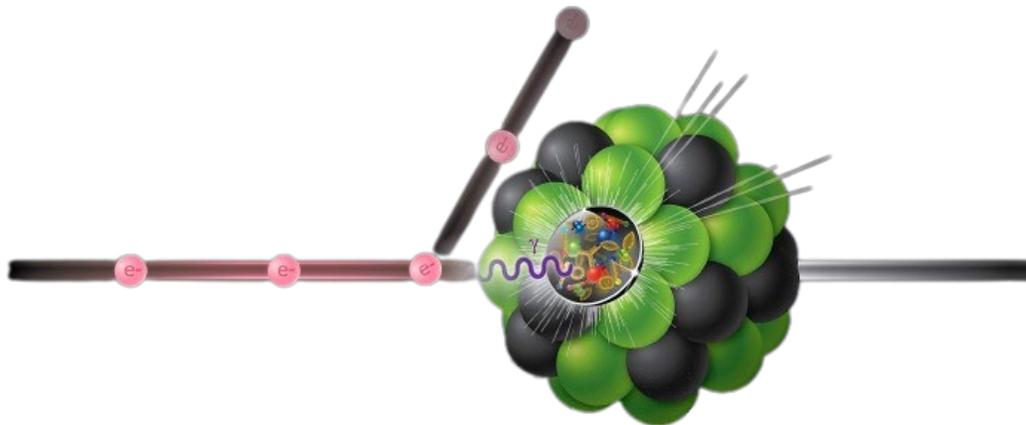
- The context: The **Electron-Ion Collider** and the **EPIC** detector
- **SiPM and radiation damage**
- First SiPM readout system
- **Characterization and Test beam results**
- Towards the final system



# The Electron-Ion Collider

## The major US project in the field of nuclear physics

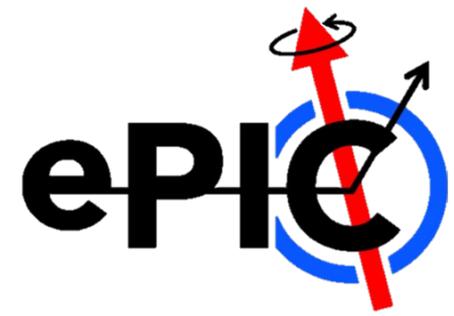
- one of the most important scientific facilities for the future of nuclear and subnuclear physics
- **the world's first collider for**
  - polarized electron-proton (and light ions)
  - electron-nucleus collisions
- **will allow to explore the secrets of QCD**
  - understand origin of mass & spin of the nucleons
  - extraordinary 3D images of the nuclear structure



**protons and nuclei**  
use **RHIC**  
infrastructure

**polarized electrons**  
new accelerator  
complex and storage  
ring

# The ePIC detector



## Magnet

- New 1.7 T SC solenoid, 2.8 m bore diameter

## Tracking

- Si Vertex Tracker MAPS wafer-level stitched sensors (ALICE ITS3)
- Si Tracker MAPS barrel and disks
- Gaseous tracker: MPGDs ( $\mu$ RWELL, MMG) cylindrical and planar

## PID

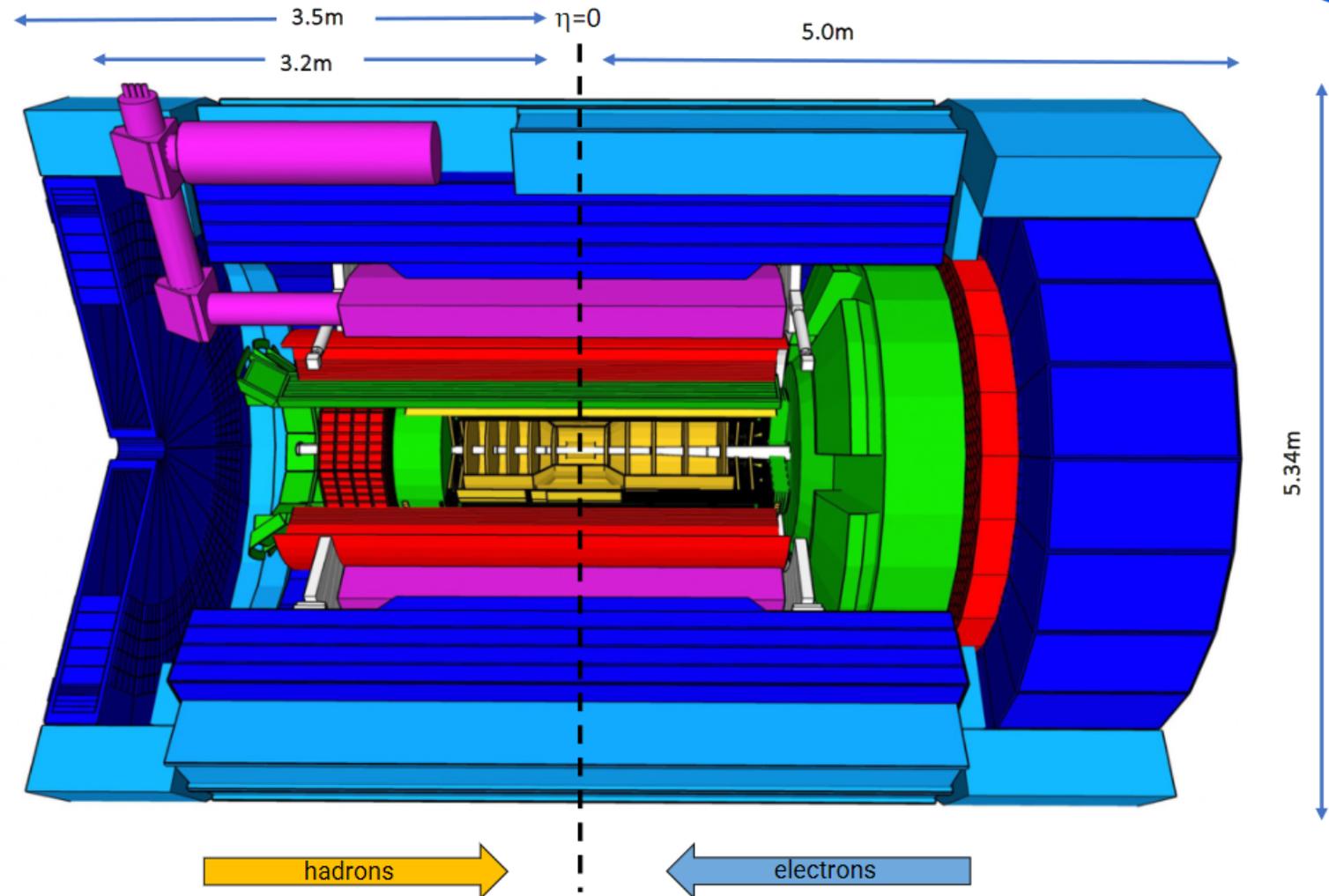
- high performance DIRC (hpDIRC)
- dual RICH (aerogel + gas) (forward)
- proximity focussing RICH (backward)
- ToF using AC-LGAD (barrel+forward)

## EM Calorimetry

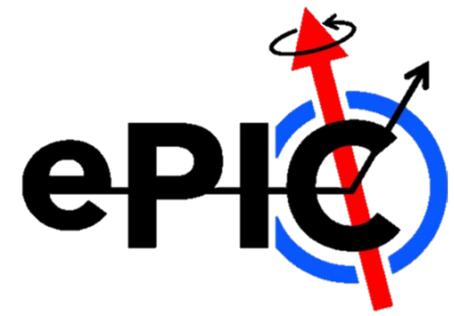
- imaging EMCal (barrel)
- W-powder/SciFi (forward)
- $\text{PbWO}_4$  crystals (backward)

## Hadron calorimetry

- FeSc (barrel, re-used from sPHENIX)
- Steel/Scint – W/Scint (backward/forward)



# The ePIC detector



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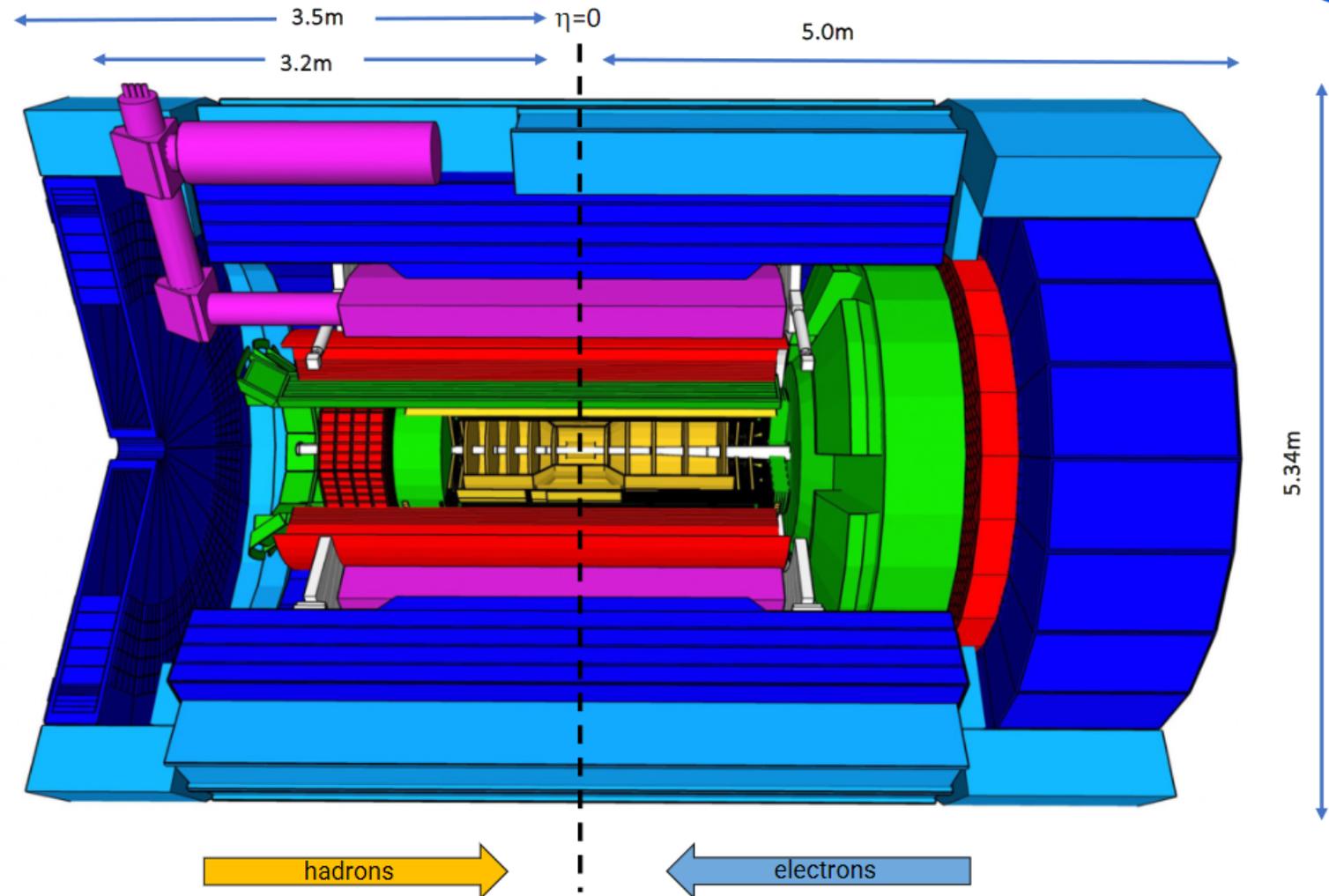
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# The dual-radiator (dRICH) for forward PID

Compact and cost-effective solution for broad momentum (3-50 GeV/c) coverage at forward rapidity

$\pi/K$   $3\sigma$  separation at 50 GeV/c

**RADIATORS:** aerogel ( $n \sim 1.02$ ) and  $C_2F_6$  ( $n \sim 1.0008$ )

**MIRRORS:** 6 open sectors of large outward-reflecting

**Photosensors:**  $3 \times 3$  mm<sup>2</sup> pixels  $0.5$  m<sup>2</sup> per sector in 1 T magnetic field and radioactive environment ( $10^{11}$  n<sub>eq</sub>/cm<sup>2</sup> total exposure 12 y operation) for low light levels.

**SiPM** is the best **photosensor candidate:**

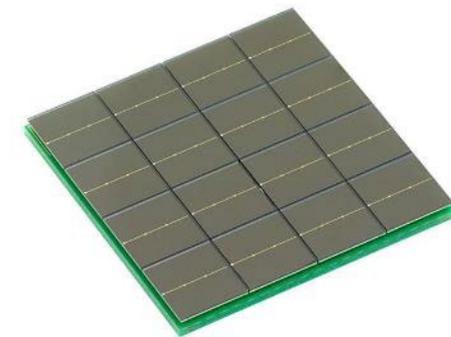
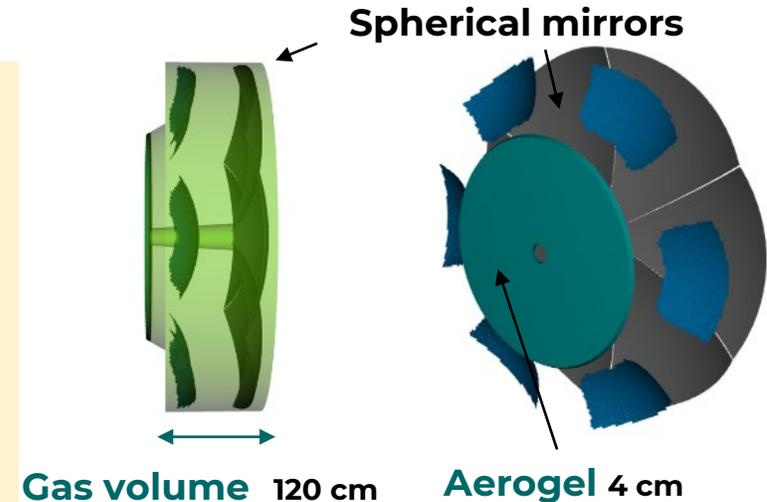
**Single Photon sensitivity**  $\sim 10$  phs per Cherenkov event

Good **timing** performance  $< 100$  ps

**Cheap** and **insensitive** to **magnetic** fields

**BUT**

**High DCR** and **high radiation sensitivity**



# The dual-radiator (dRICH) for forward PID

Compact and cost-effective solution for broad momentum (3-50 GeV/c) coverage at forward rapidity

$\pi/K$   $3\sigma$  separation at 50 GeV/c

Spherical mirrors

RADIATORS: ae

MIRRORS: 6 op

Photosensors:

magnetic field a

$n_{eq}/cm^2$  total ex

SiPM is the best

Single Photon s

Good timing pe

Cheap and inse

BUT

High DCR and high radiation sensitivity

## What can be done?

**Cooling** the sensors down to  $-30^\circ\text{C}$  reduces the DCR by a factor  $\sim 100$



**Radiation damage** by Non-ionizing Energy Loss (NIEL) leads to **displacement** damages and build up of **crystal defects** that results in increased DCR but performance can be recovered by using **annealing** techniques (**high temperature**).

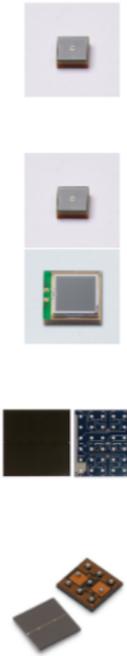


**Sub ns time resolutions** allow **coincidence** cuts that greatly reduces DCR contribution in the measurements



# Extensive studies on different kind of SiPM from different vendors (more than 200 devices tested)

board	sensor	uCell (μm)	V <sub>bd</sub> (V)	PDE (%)	DCR (kHz/mm <sup>2</sup> )	window	notes
HAMA1	S13360 3050VS	50	53	40	55	silicone	legacy model Calvi et. al
	S13360 3025VS	25	53	25	44	silicone	legacy model smaller SPAD
HAMA2	S14160 3050HS	50	38	50		silicone	newer model lower V <sub>bd</sub>
	S14160 3015PS	<u>15</u>	38	32	78	silicone	smaller SPADs radiation hardness
SENSL	MICROFJ 30035	35	24.5	38	50	glass	different producer and lower V <sub>bd</sub>
	MICROFJ 30020	20	24.5	30	50	glass	the smaller SPAD version
BCOM	AFBR S4N33C013	30	27	43	111	glass	commercially available FBK-NUVHD

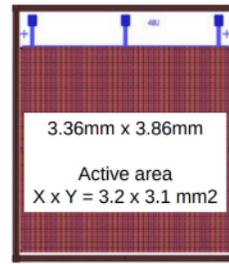


PHOTON IS OUR BUSINESS





## NUV-HD-CHK



3.36mm x 3.86mm  
Active area  
X x Y = 3.2 x 3.1 mm<sup>2</sup>

NUV-HD big cells

Technology similar to NUV-HD-Cryo  
Optimized for single photon timing

- Cell pitch 40 μm
- High PDE > 55%
- Primary DCR @ +24°C ~ 50 kHz/mm<sup>2</sup>
- Correlated noise 35% @ 6 V

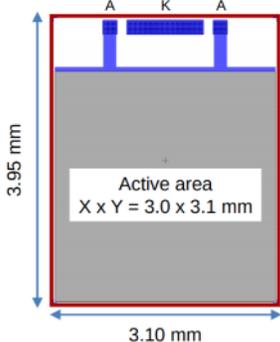
October 5, 2020

FBK - Confidential





## NUV-HD-RH



3.95 mm  
Active area  
X x Y = 3.0 x 3.1 mm  
3.10 mm

NUV-HD-RH

Technology under development  
optimized for radiation hardness in  
HEP experiments

- Cell pitch 15 μm with high fill factor
- Fast recovery time – reduced cell occupancy  
Tau recharge < 15 ns
- Primary DCR @ +24°C ~ 40 kHz/mm<sup>2</sup>
- Correlated noise 10% @ 6 V

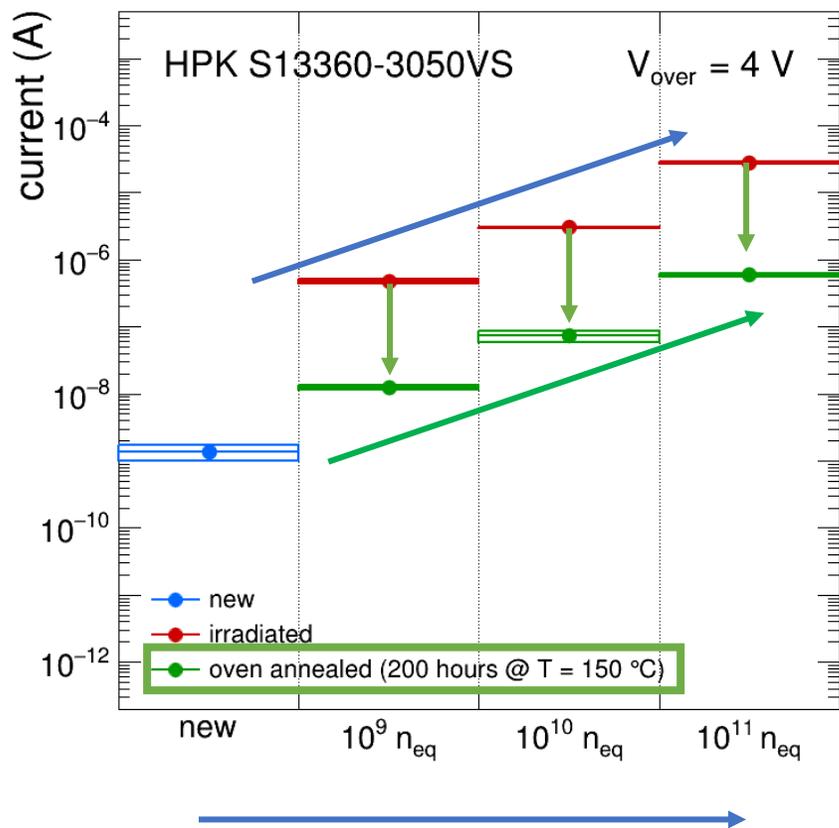
October 5, 2020

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# Irradiation-annealing campaigns findings

4 irradiation campaigns with protons and neutrons at TIFPA (TN) and LNL (PD)

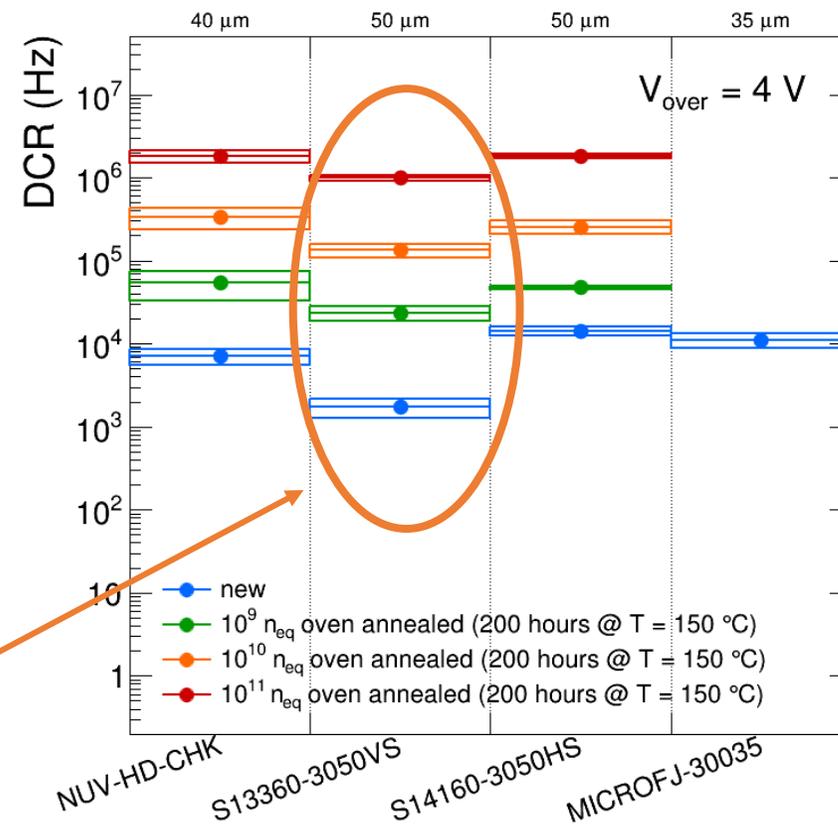


Linear **increase** of dark current/**DCR** with the dose

**~40x reduction** of dark current/**DCR** with **150° C** oven **annealing**

**Residual** increase in **DCR** is **proportional** to the dose

**All sensors** behave similarly but **HAMATSU s13-50 um** shows the **lowest DCR**



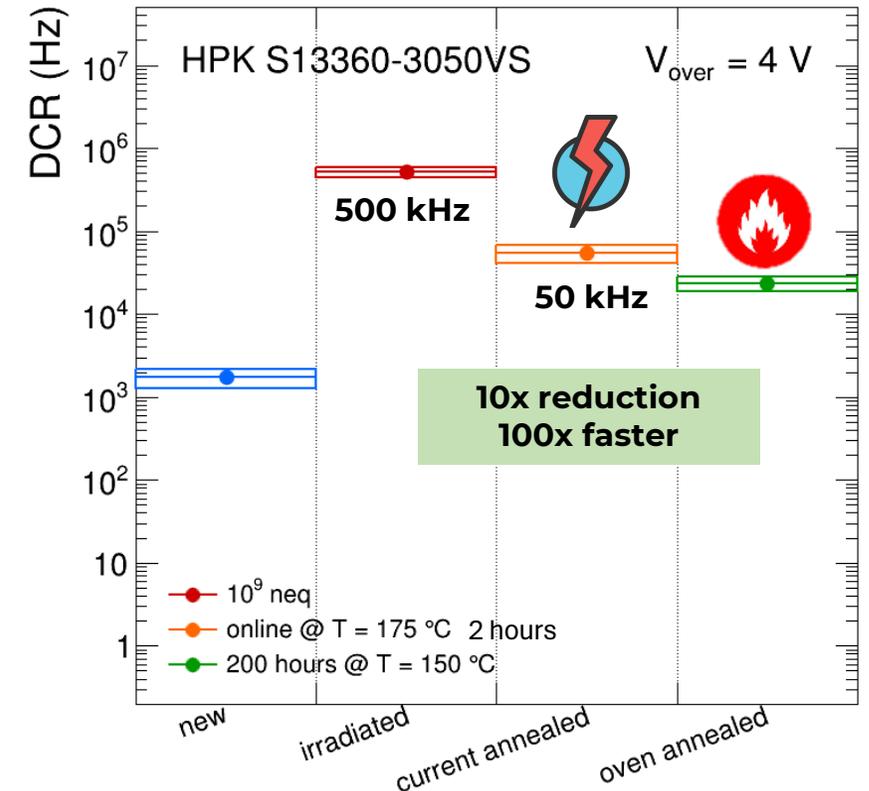
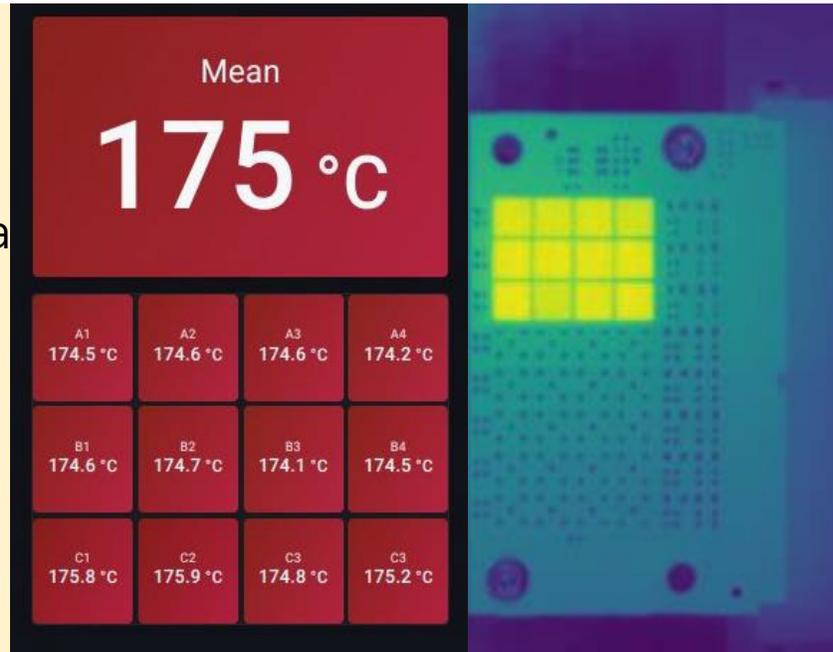
Measurements taken @  $-30^\circ C$

# Current annealing

Another way to heat up the sensors is by directly polarization. Current flowing into the SiPM, generates heat resulting in annealing.

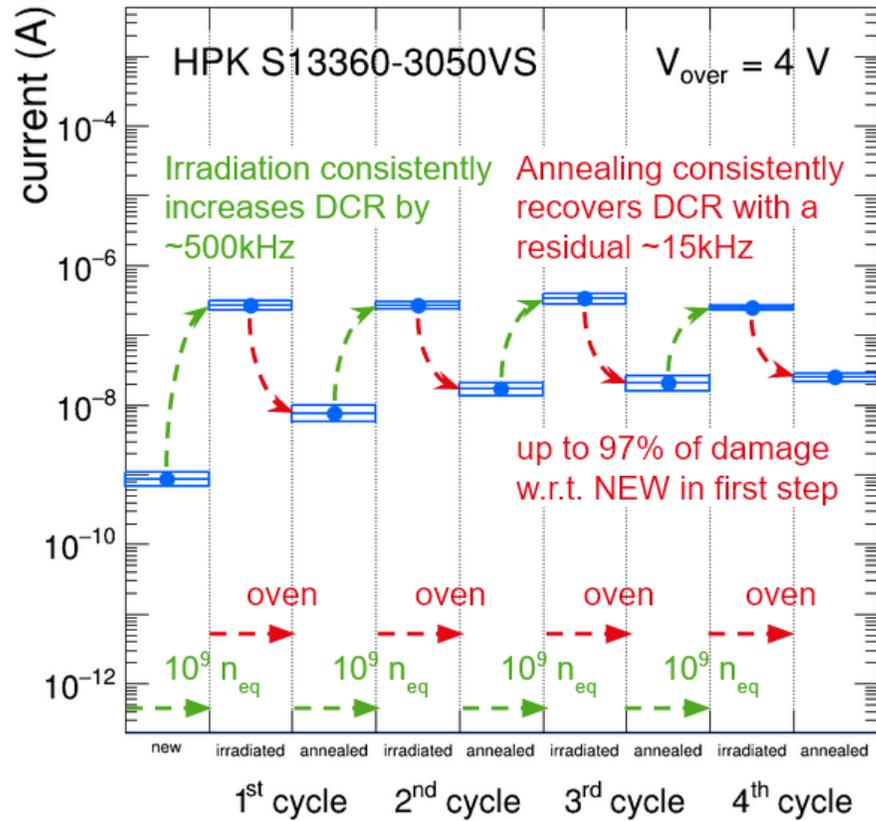
175° C can be obtained providing 10 V and ~100 mA (~ **1 W**) per sensor @ room temperature

An **IR thermal camera** provides **feedback** to a **PWM** system able to set each **SiPM temperature**

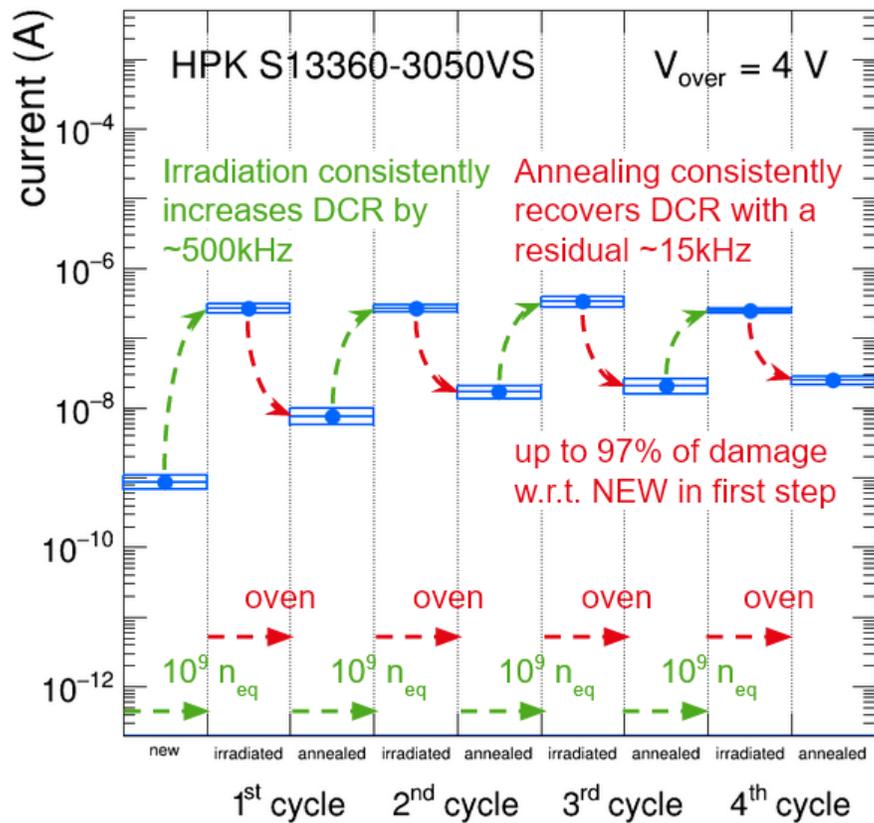


Measurements taken @ -30° C

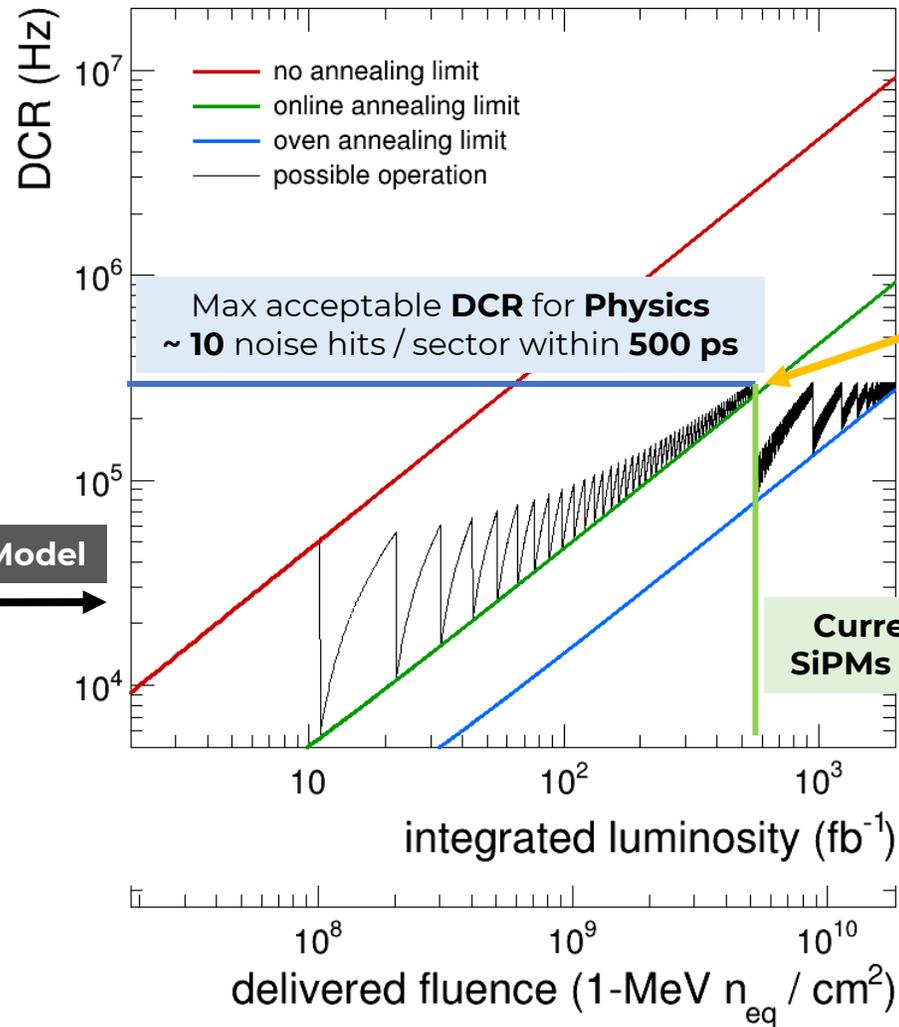
# Damage recovery of SiPMs with multiple annealing cycles



# Damage recovery of SiPMs with multiple annealing cycles

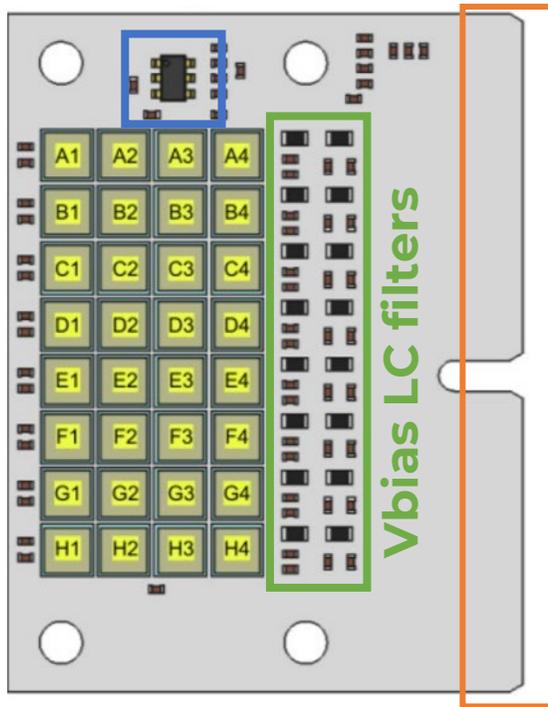


Ageing Model



# First prototype concept: flexibility

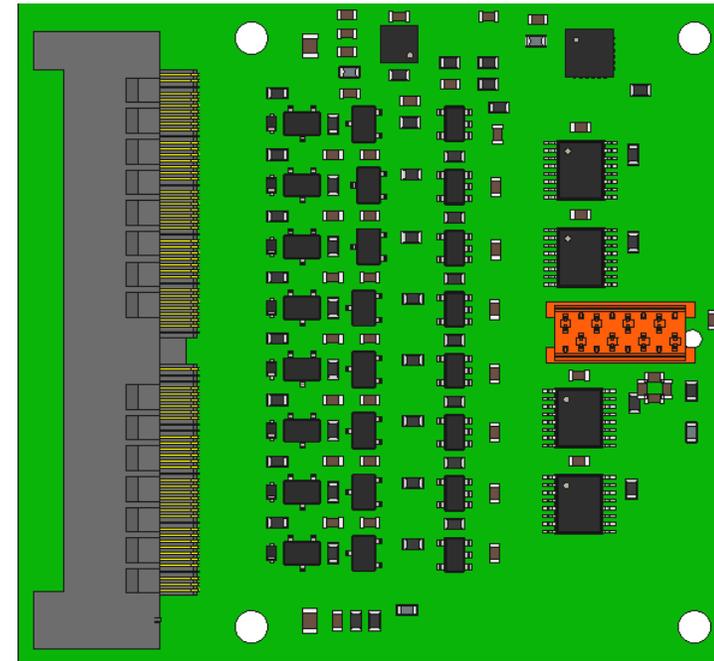
Temp. sensor (LM73)



EDGE connector

## SIPMs matrix

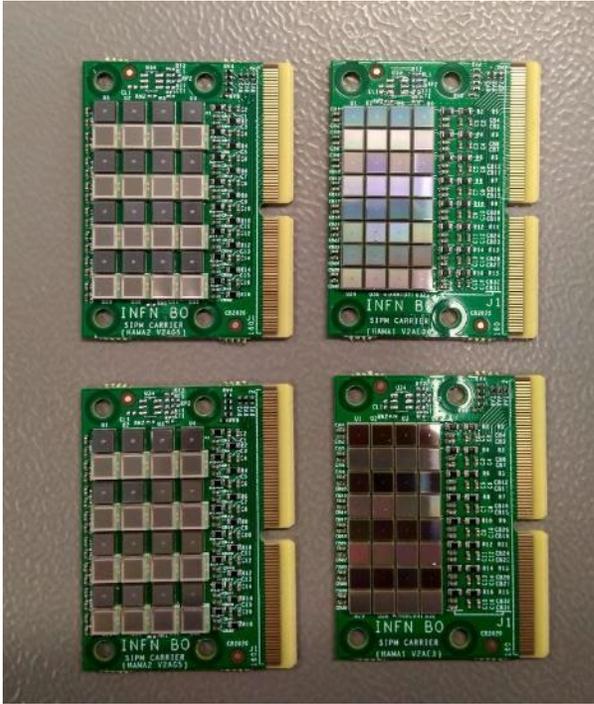
- Different sensors
- No plastic



## Adapter (INFN FE)

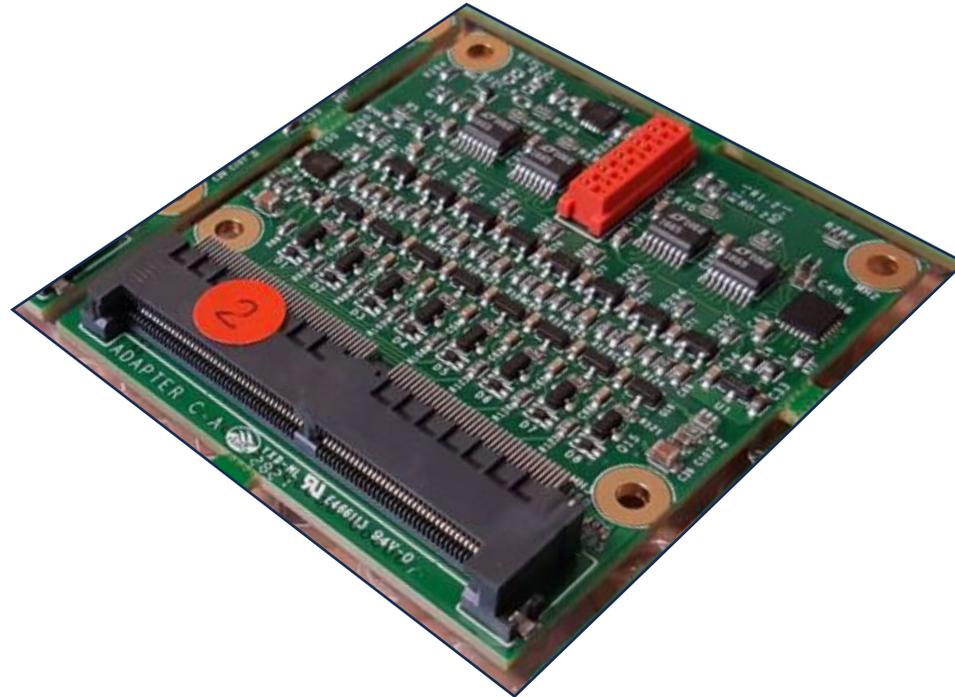
- VBias fine tuning
- AC connection to the FE

# First prototype



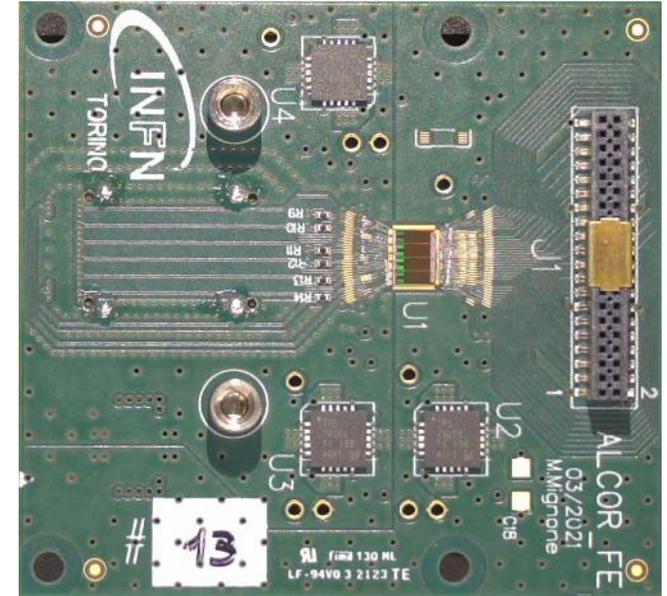
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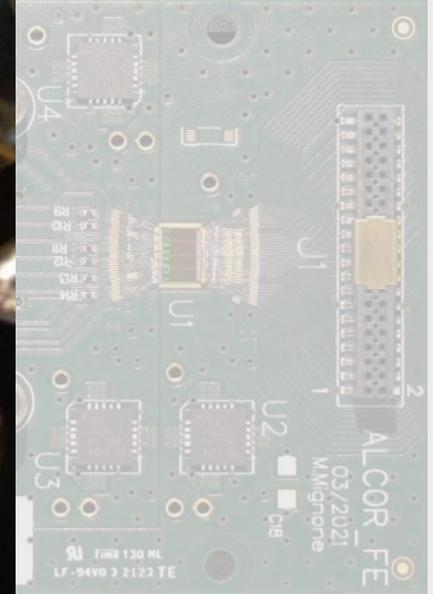
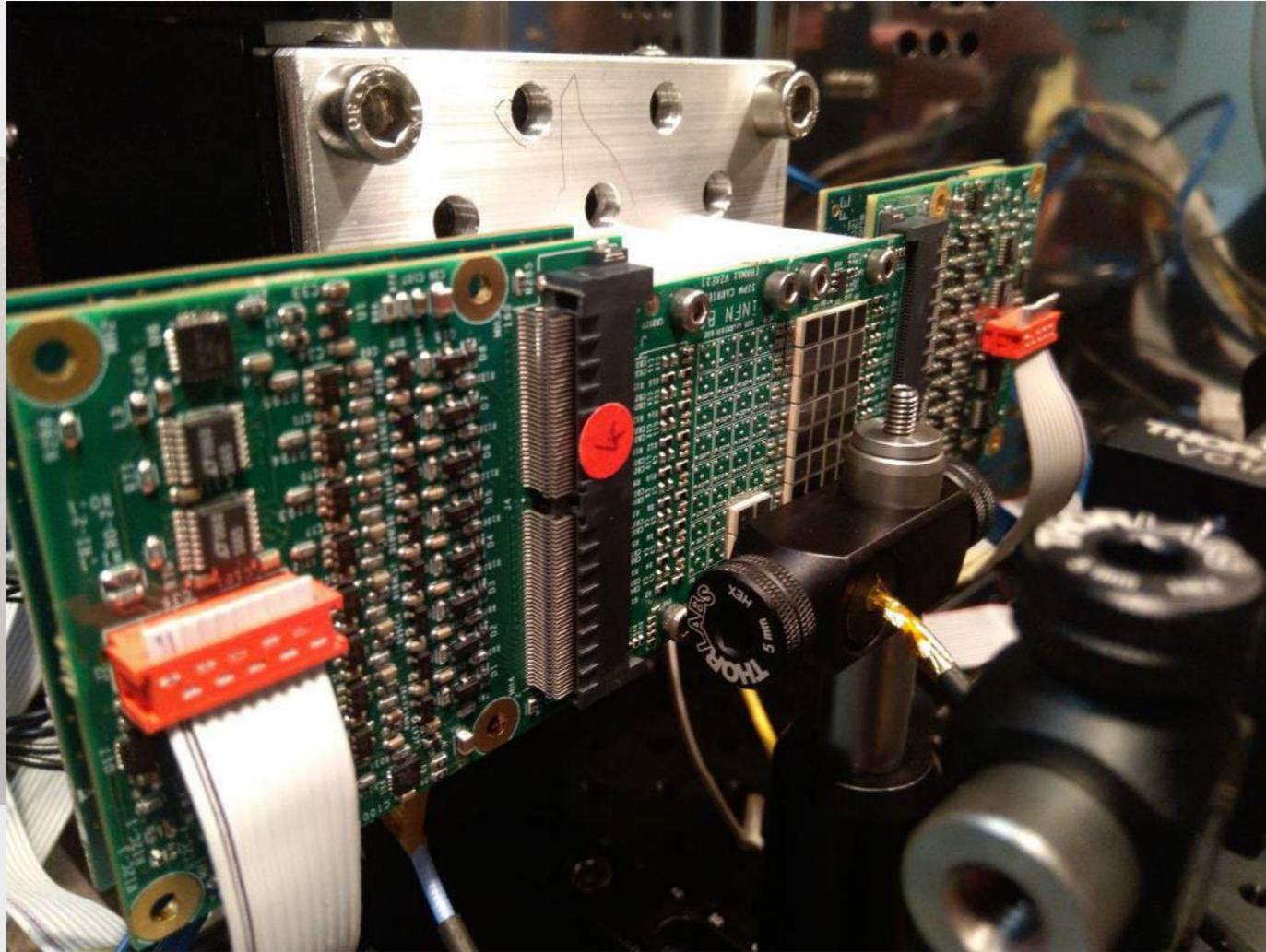
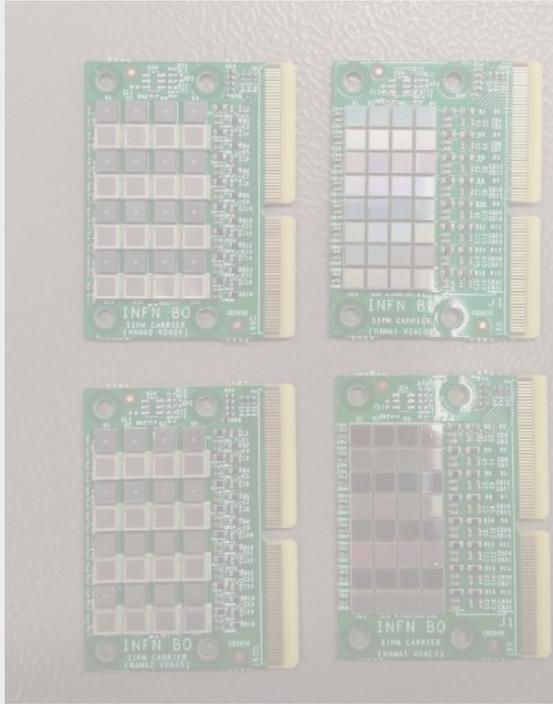
- AC connection to the FE
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## Front-End board (INFN TO)

- Alcor ASIC
- Voltage regulators
- Samtec Firefly 8x pairs to FPGA

# First prototype



## SIPMs matrix

- Different sensors
- No plastic

- AC connection to the FE
- VBias fine tuning

## (INFN TO)

- ALCOR ASIC
- Voltage regulators
- Samtec Firefly 8x LVDS pairs

# ALCOR ASIC by INFN-To

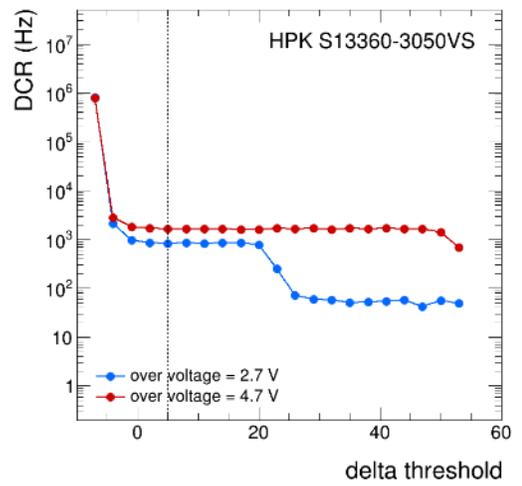
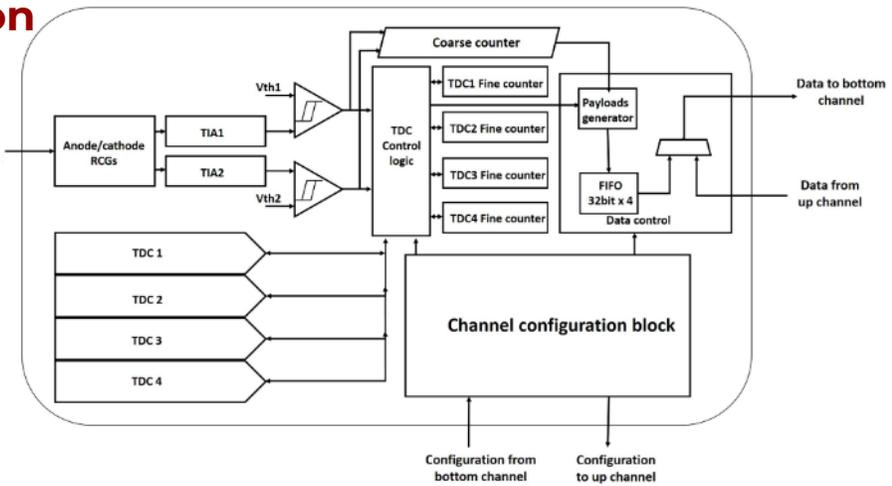
32-pixel matrix mixed signal ASIC initially foreseen for SiPMs in cryogenics

The chip performs **amplification, signal conditioning** and **event digitization** with a fully **digital I/O**

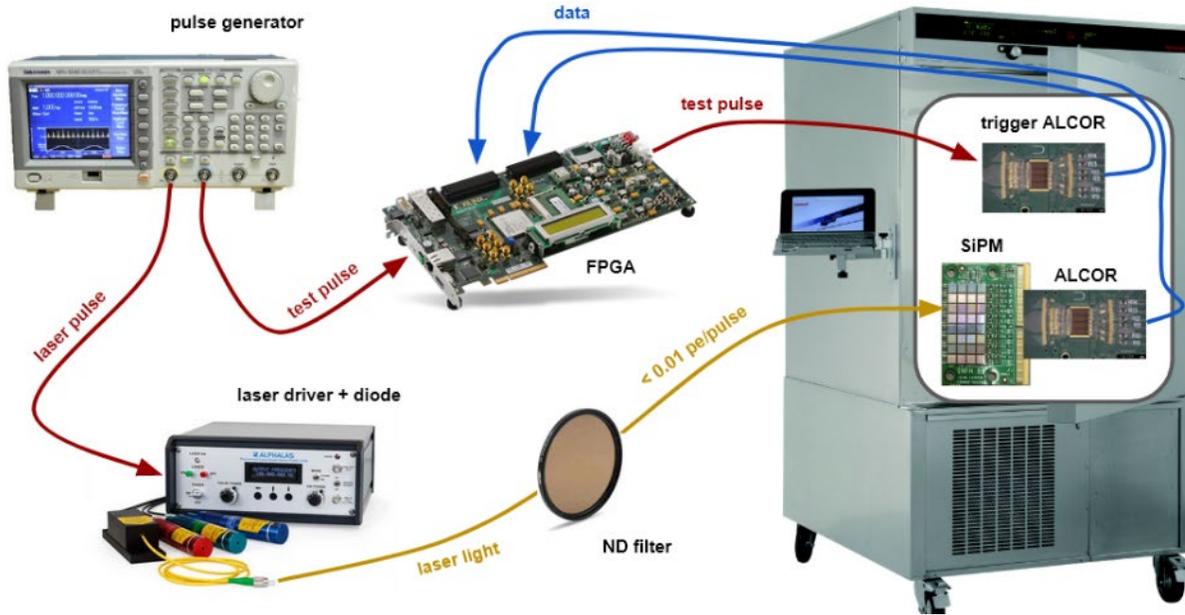
Each **pixel** features

- Regulated common gate **amplifier** (10 ohm impedance)
- Post amp TIA for **4 gain settings**
- 2 **leading-edge discriminators** with independent **threshold** settings
- 4 **TDCs** based on analogue interpolation with **50 ps LSB** (@ 320 MHz)
- 3 **triggerless operation** modes:
  - **LET** leading edge threshold measurement, high-rate time-stamp
  - **ToT** Time-over-Threshold
  - **Slew rate** measurements for signal characterization

Fully **digital output** on **4 LVDS TX** data links  
**SPI-based** chip configuration  
**64-bit** event and **status** data



# Timing performance



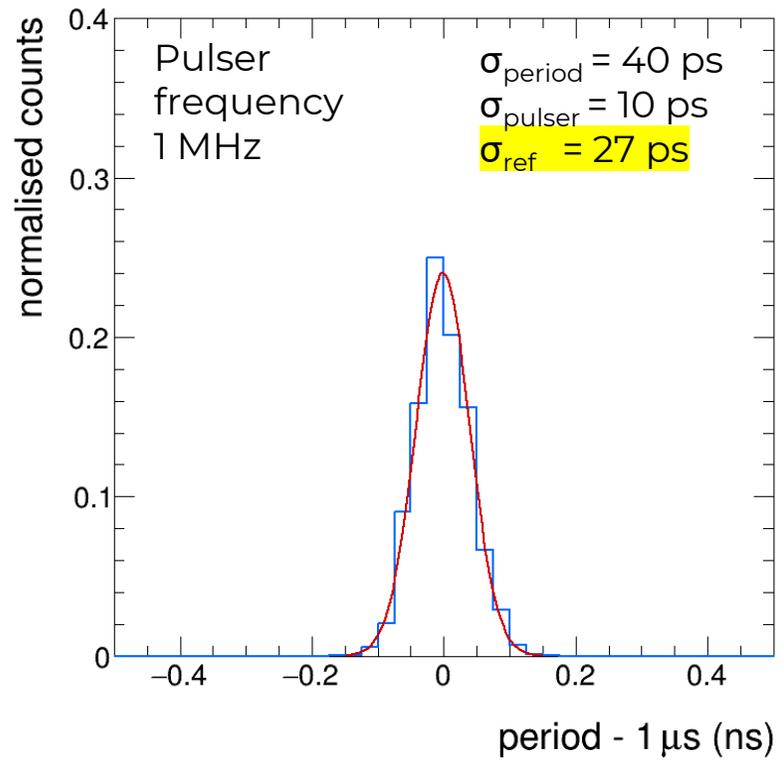
## The setup

Climatic chamber @  $-30^{\circ}\text{C}$  hosting the readout system with **SiPMs** and one without used as reference.

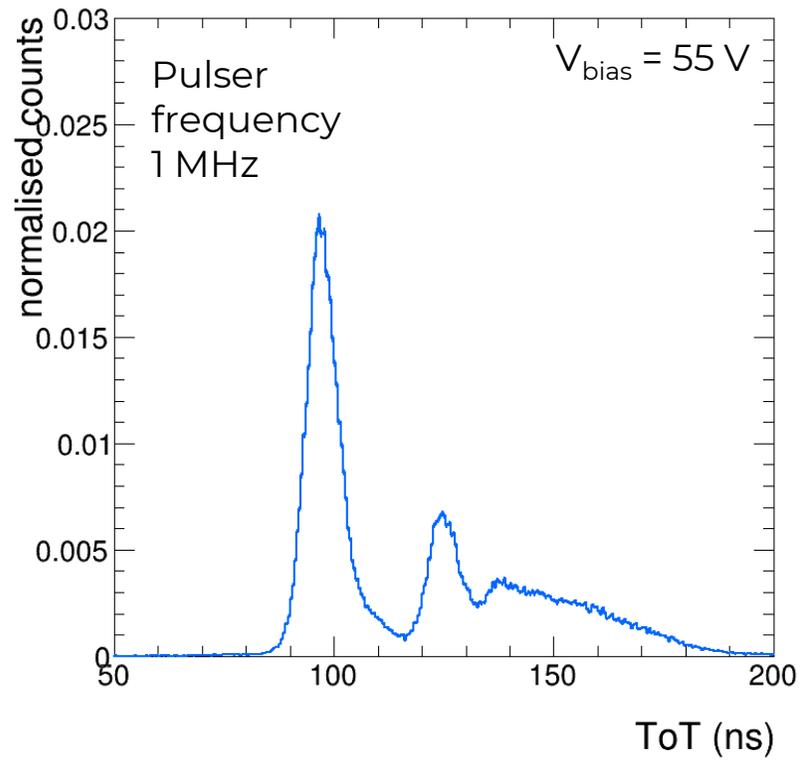
$< 4$  ps laser pulse filtered down to single photon by ND filters.

**Laser-SiPM** signal **synchronization** by sending test **pulse** to **reference ALCOR** to measure laser pulse start (50 ps LSB TDC) in synch with ALCOR readout.

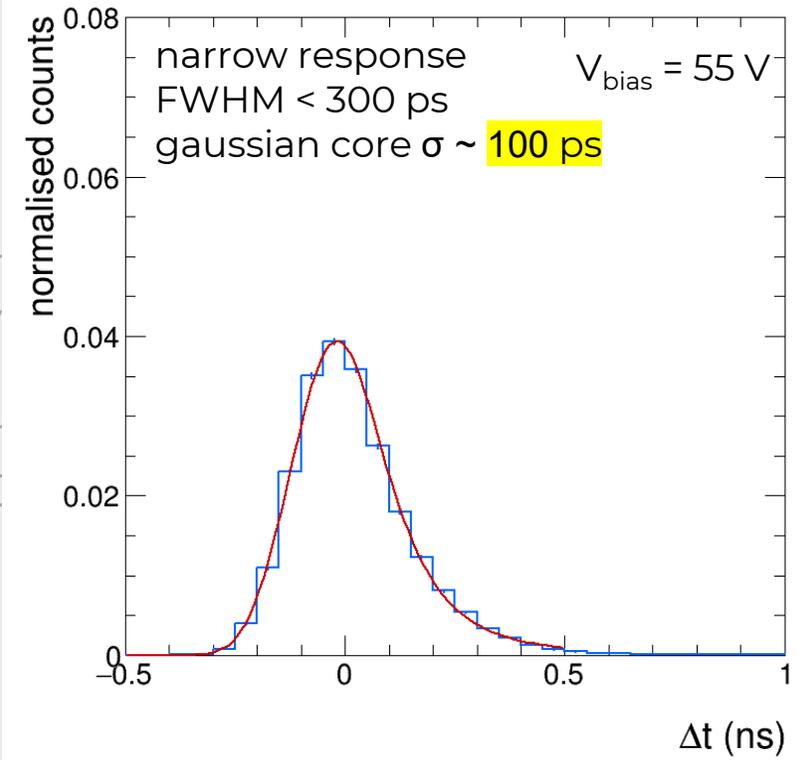
$\Delta t$  is measured as the time difference between reference and ALCOR reading SiPM



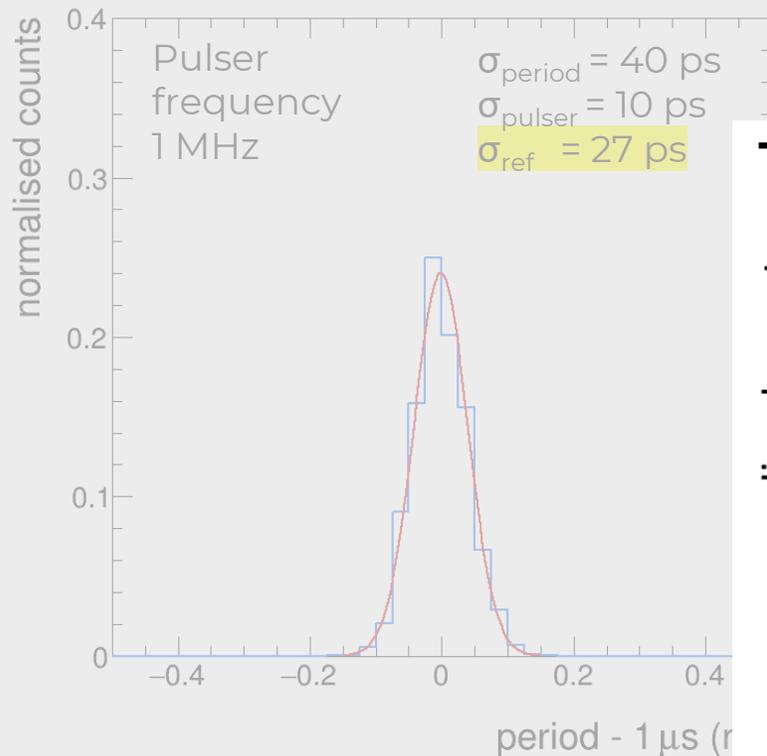
Reference ALCOR pulse period



Time-over-Threshold values

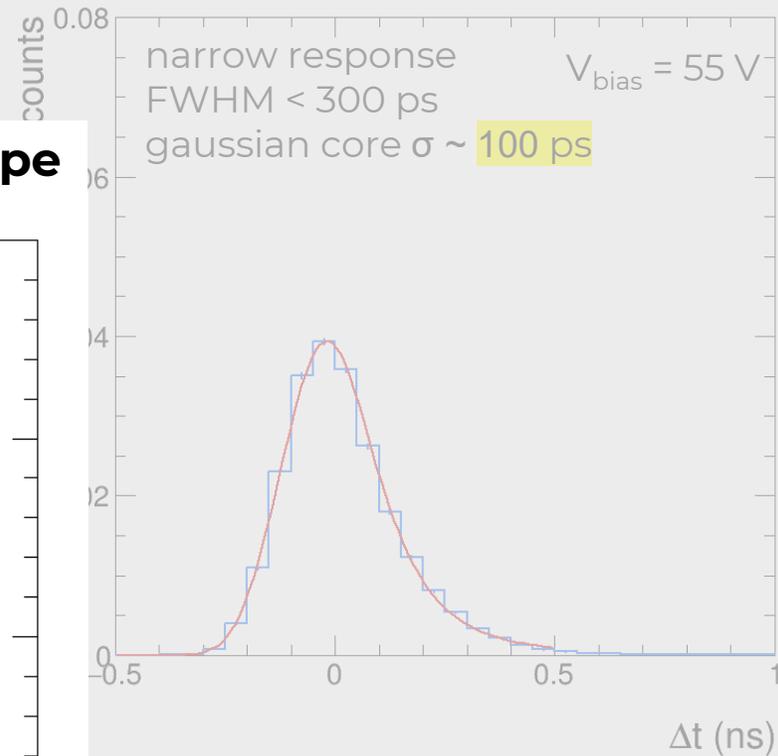
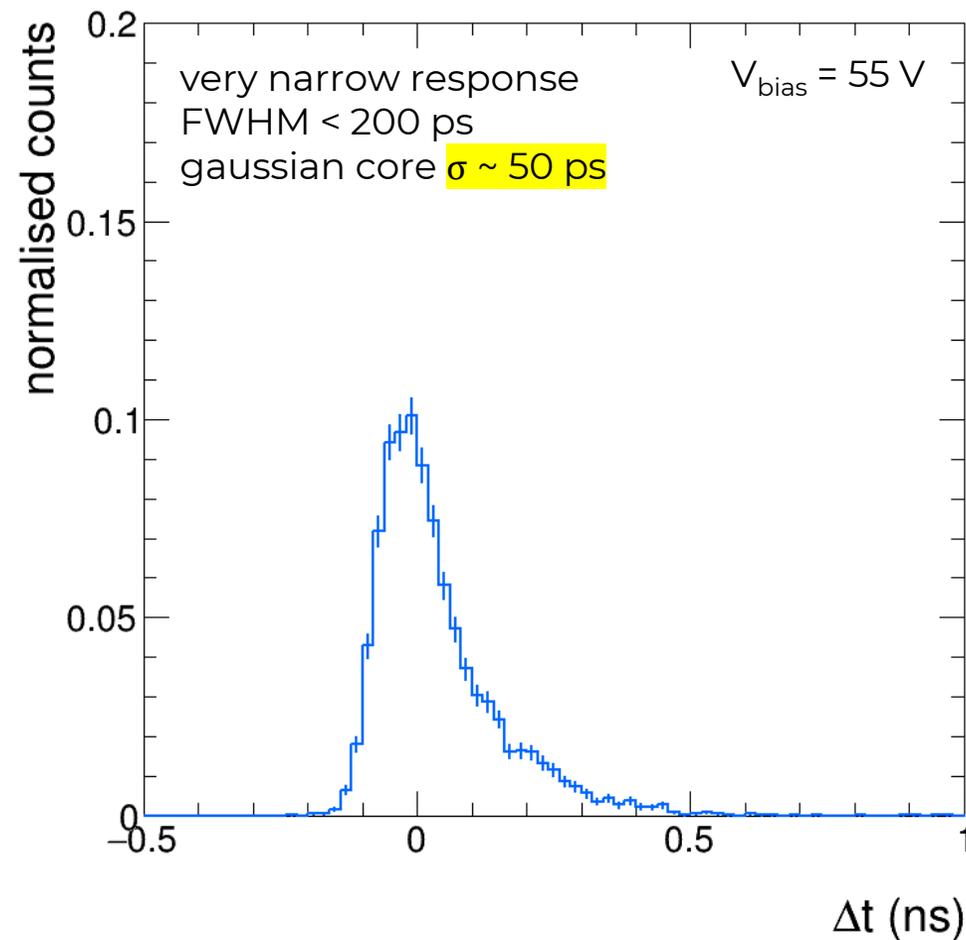


Laser-SiPM correlations (time-walk corrected)



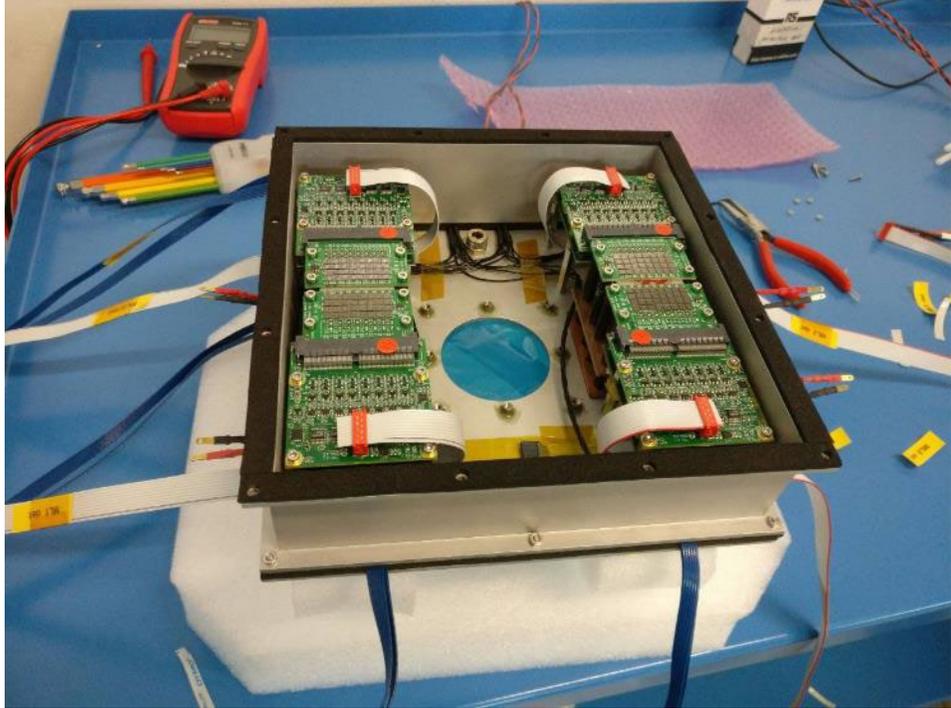
Reference ALCOR pulse period

## Time jitter measured with oscilloscope



Laser-SiPM correlations (time-walk corrected)

# 2022 test beam prototype at CERN-PS



## First prototype readout

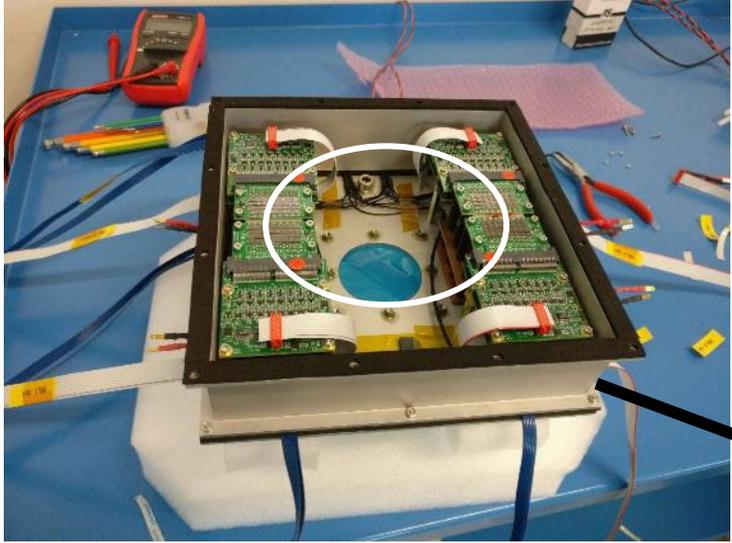
**4 matrixes** with different **SiPMs irradiated** at  $10^{10} \text{ n}_{\text{eq}}/\text{cm}^2$   
**annealed** in the oven (200 h @150° C)

- **30° C** operation with peltier cells

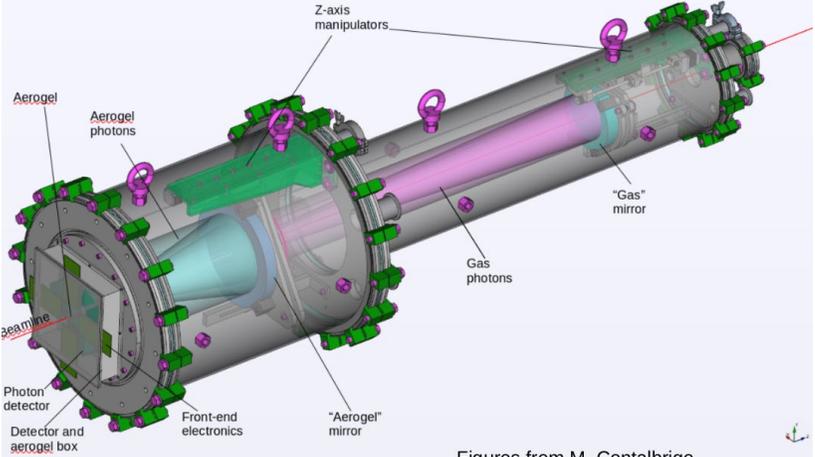
**Nitrogen** gas circulation in the box to **avoid moisture** and **frost**

Neoprene on the edges to isolate the sensors from light

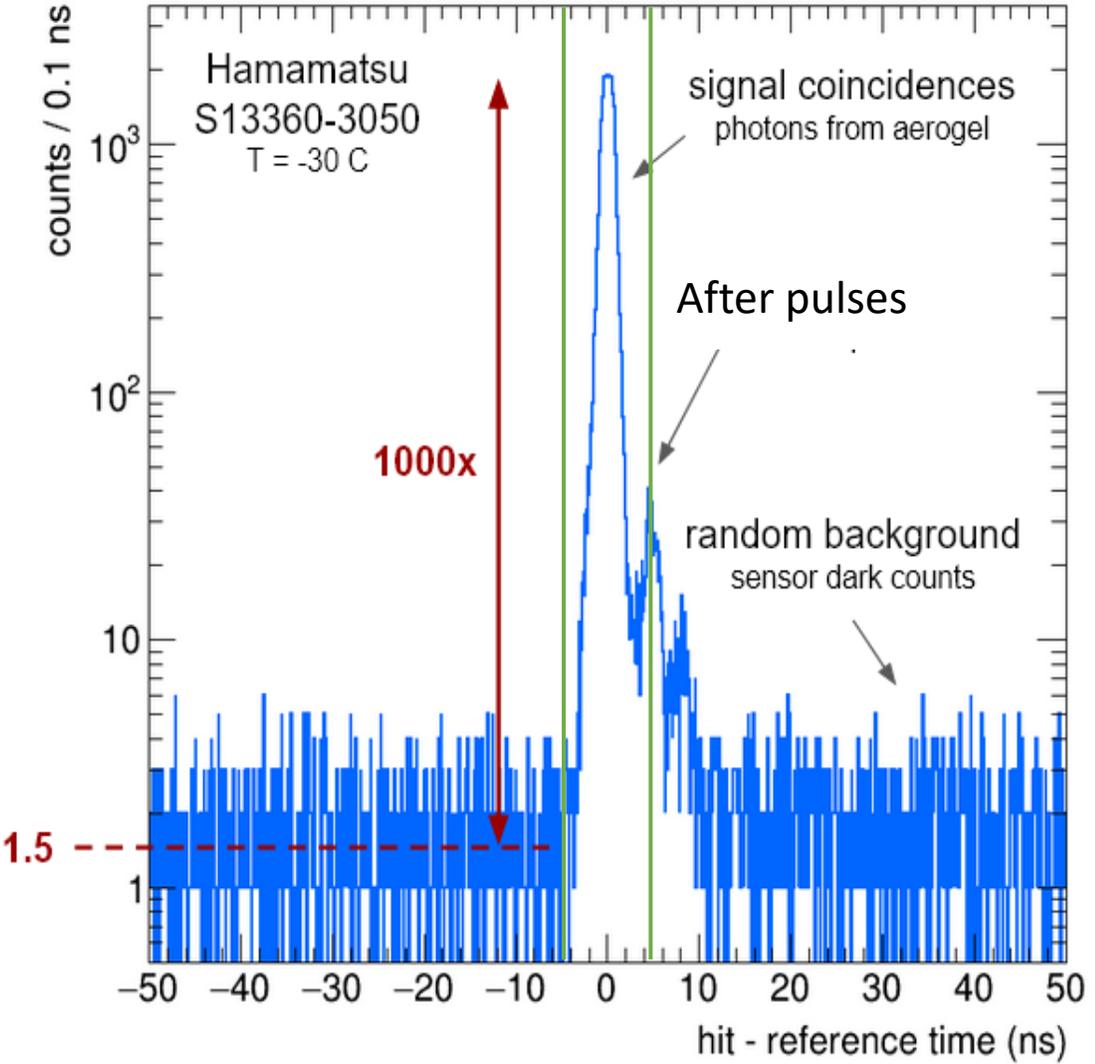
# 2022 test beam prototype at CERN-PS



Readout box mounted onto the dRICH prototipe on PS beamline

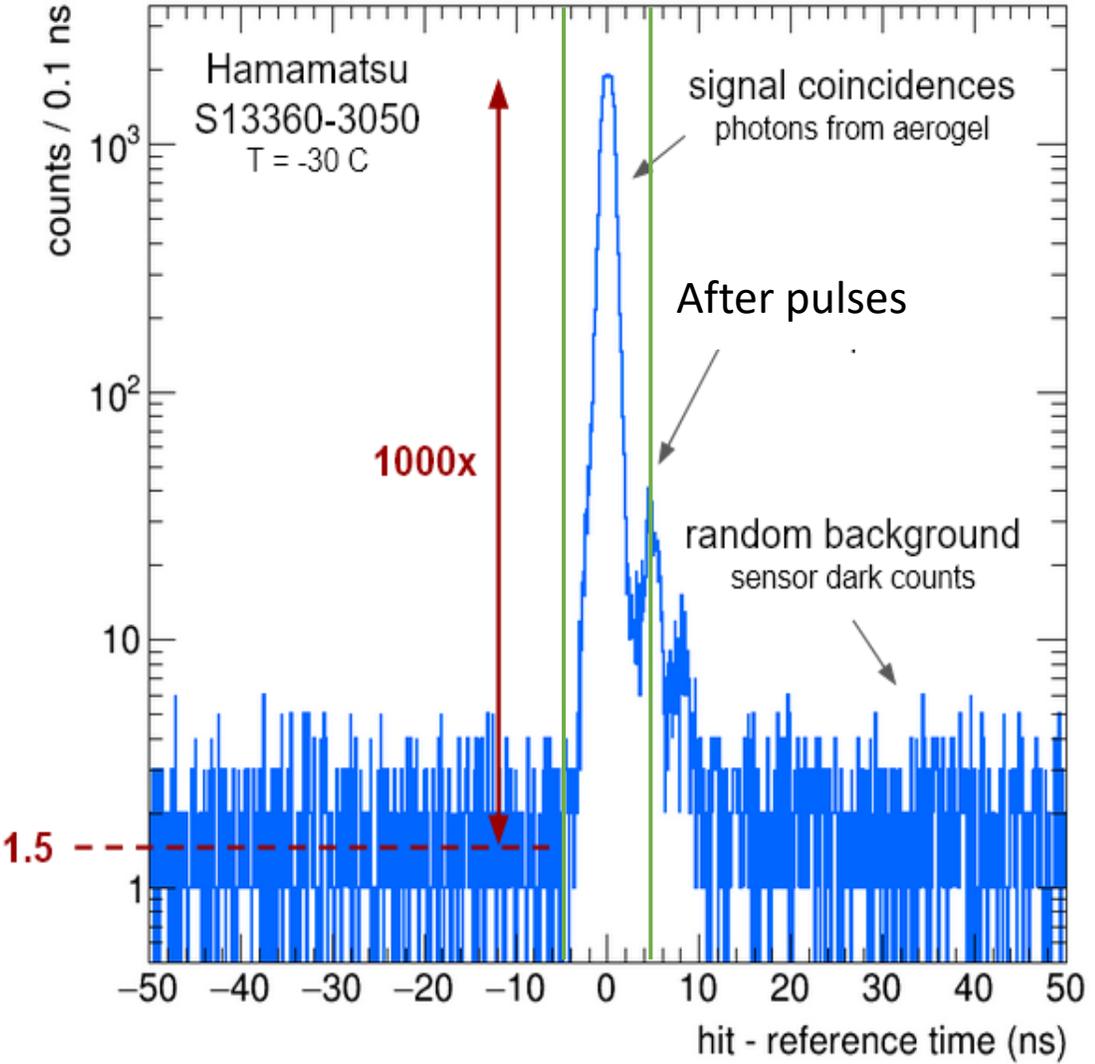


# 2022 test beam prototype at CERN-PS

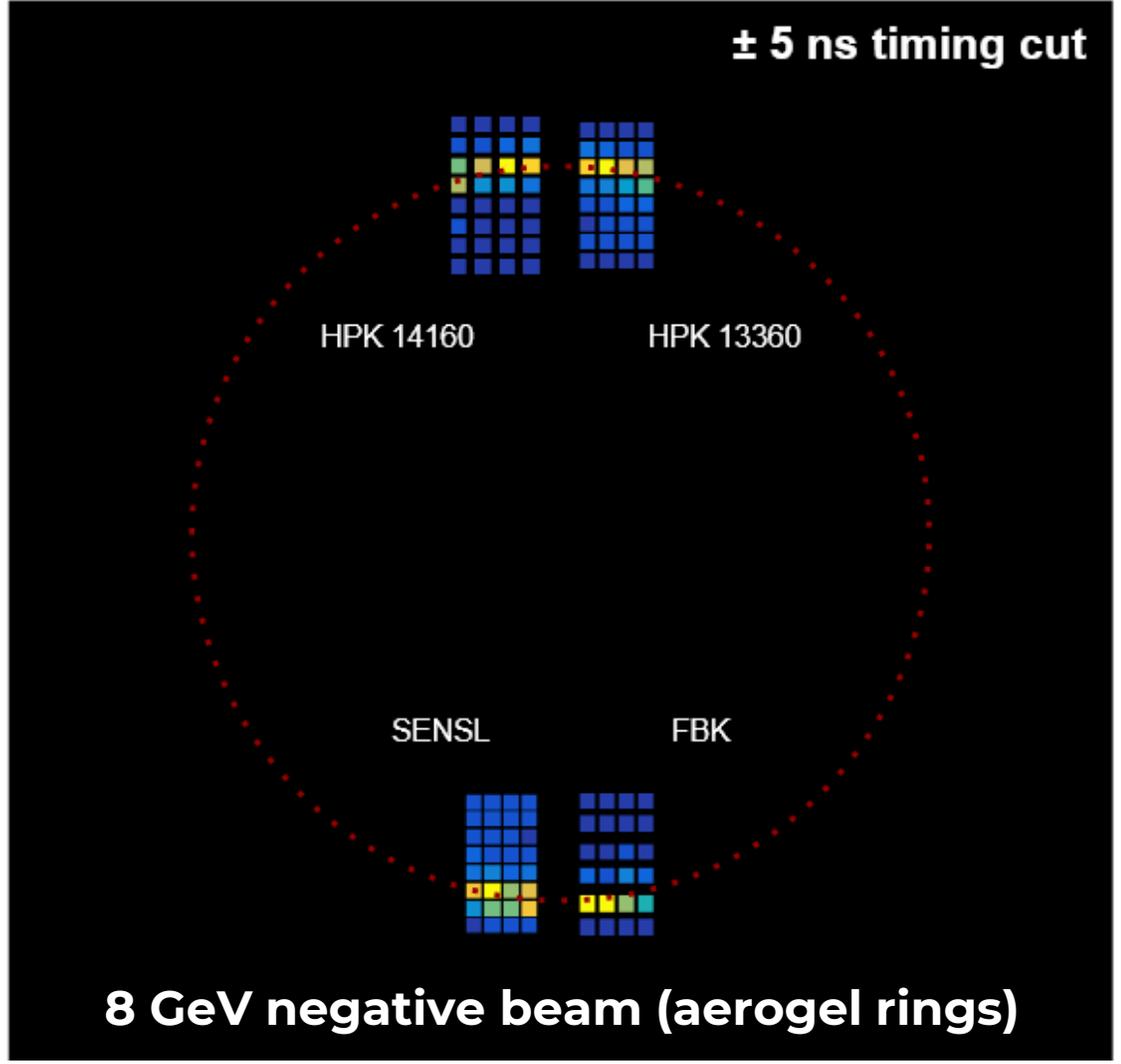


sensor DCR ~ 15 kHz

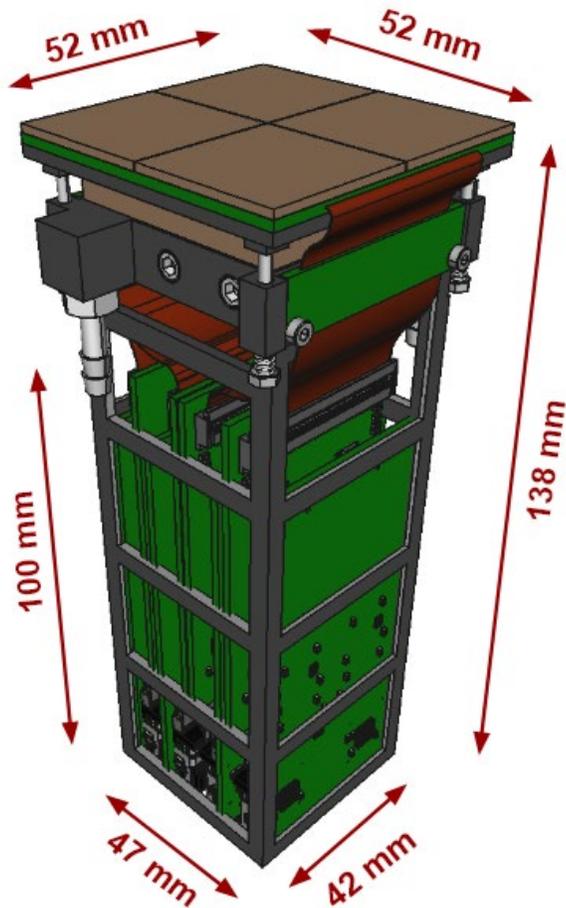
# 2022 test beam prototype at CERN-PS



sensor DCR ~ 15 kHz



# 2023 readout system prototype

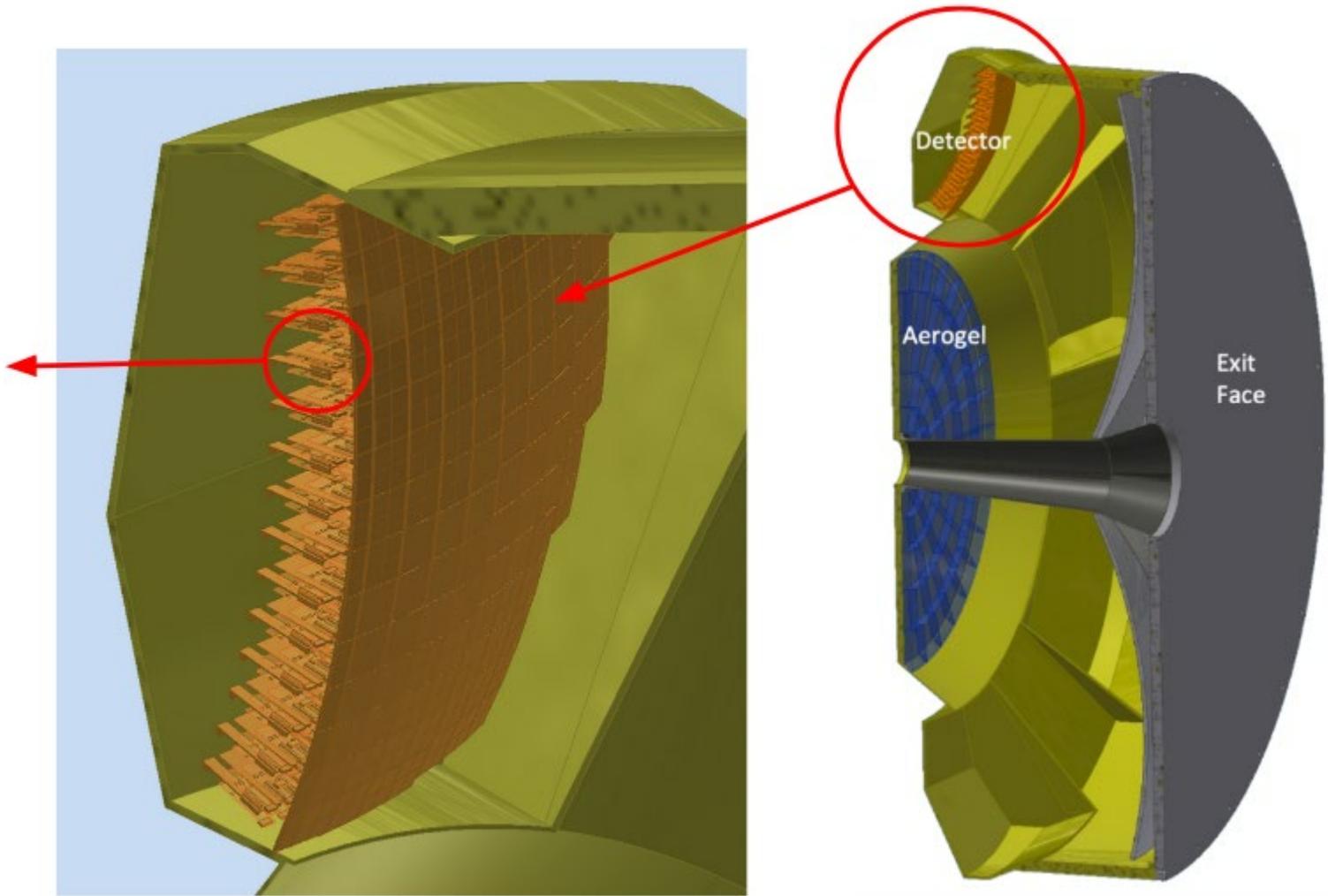
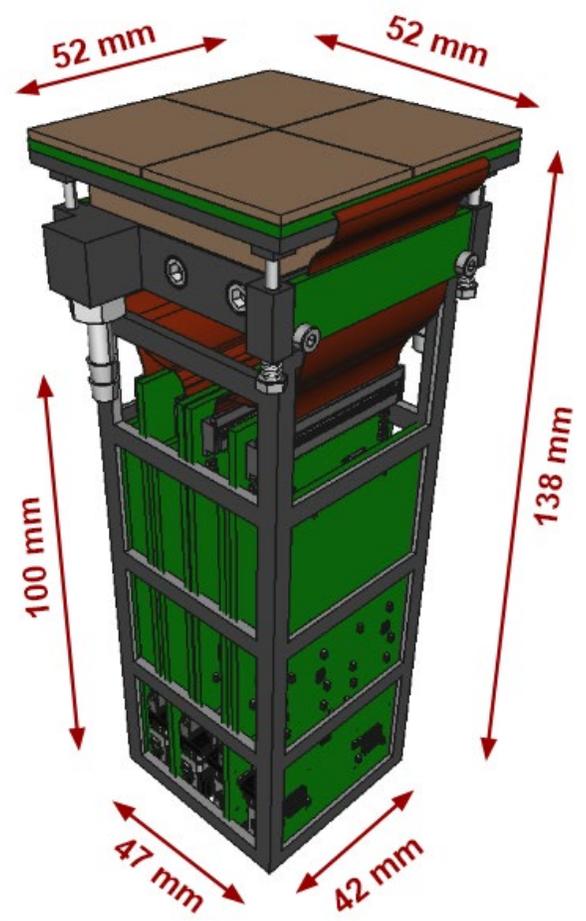


Towards the final design looking for **Compactness** and **Integration**

**4** matrixes of **8x8** Hamamtsu S13650 **SiPMs** (256) hosted by a **Rigid flex** matrix board with **no plastic** connectors (can be annealed in the oven)

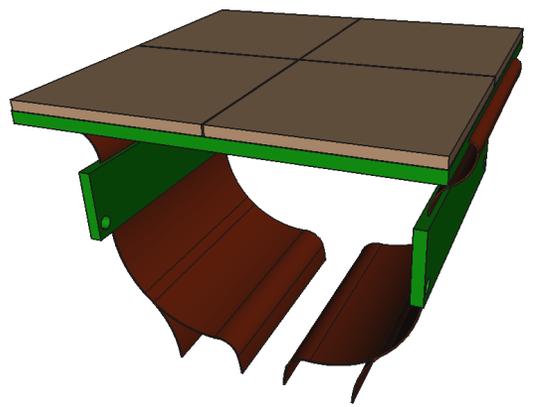
**Integrated cooling** with peltier cells and liquid cooling  
**4** stackable **adapters+frontened** boards placed perpendicularly to save space.

# 2023 readout system prototype



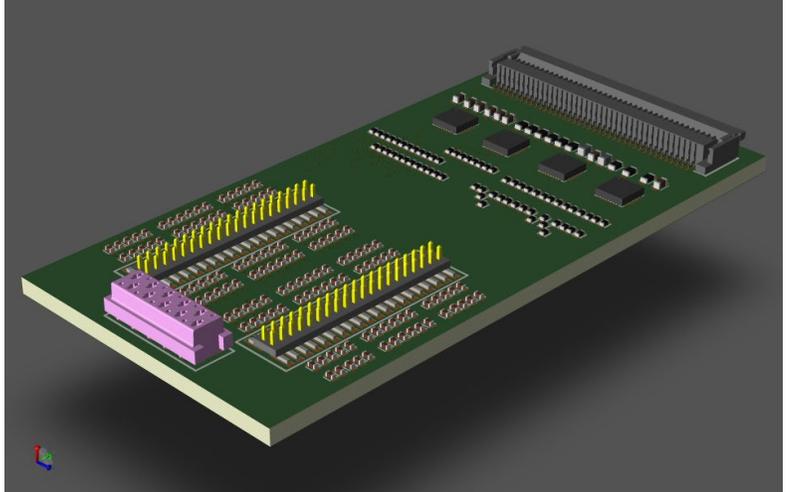
# 2023 readout system prototype

### Matrix board



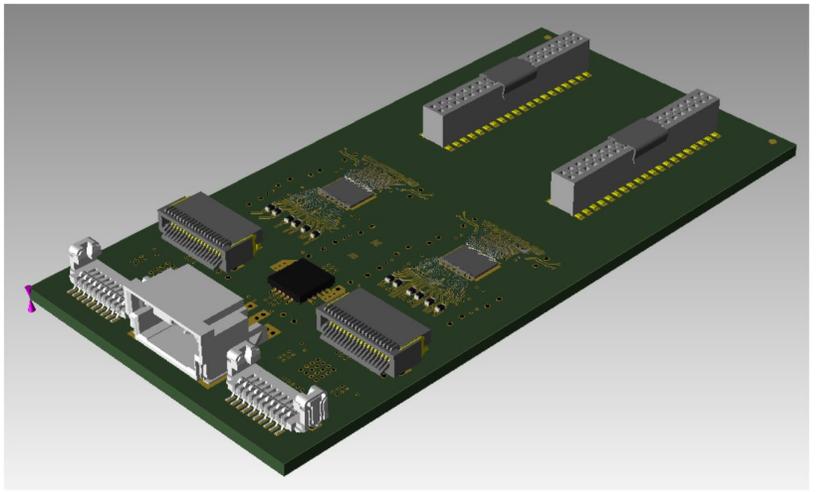
HV and signals via **flex** pcb with 1 mm bending radius  
Rigid flex design to host HV LC-filters  
Back-side temperature sensors

### 4x Adapter boards

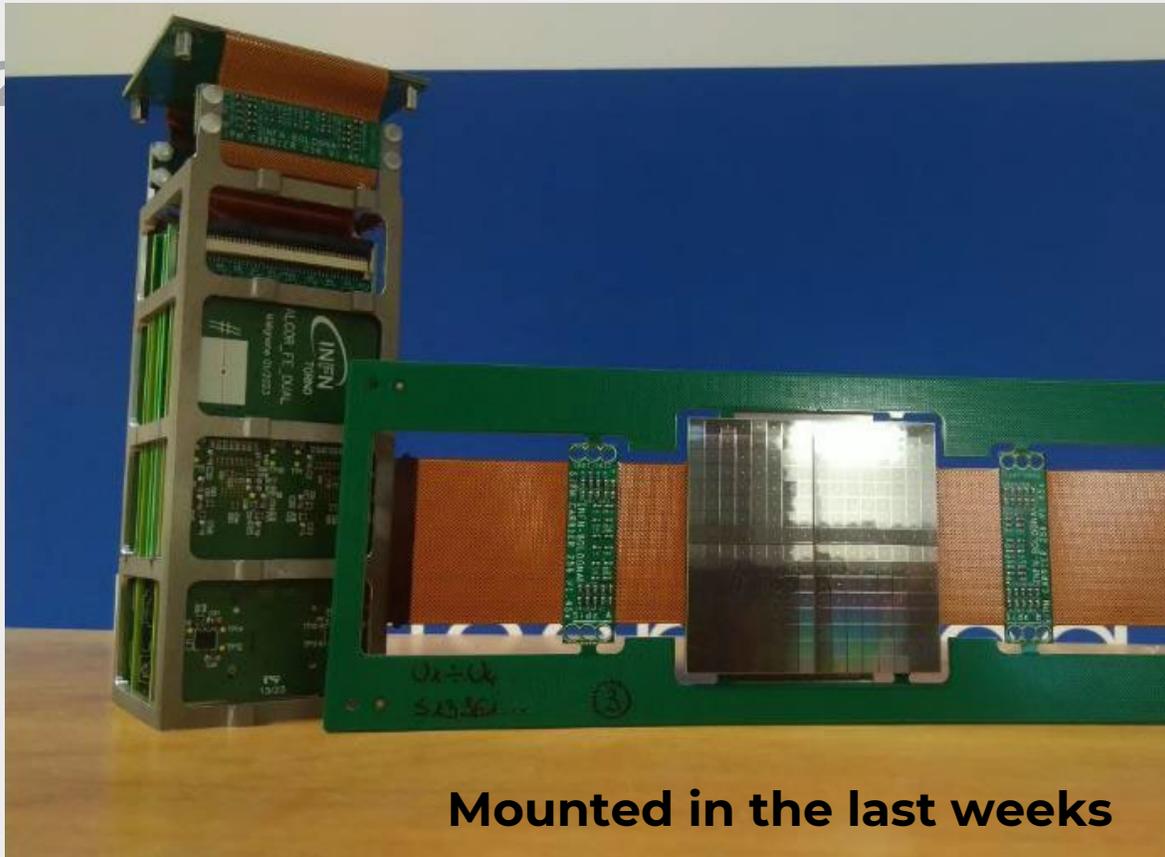


HV regulation  
0-5 V per SiPM  
0-80 V for 8 channels  
AC coupling to ALCOR  
Mosfet to isolate the anode for the “annealing mode”

### 4x Front-end boards



2x ALCOR-v2 ASICs (2x 32 channels)  
2x Firefly connectors  
Voltage regulators



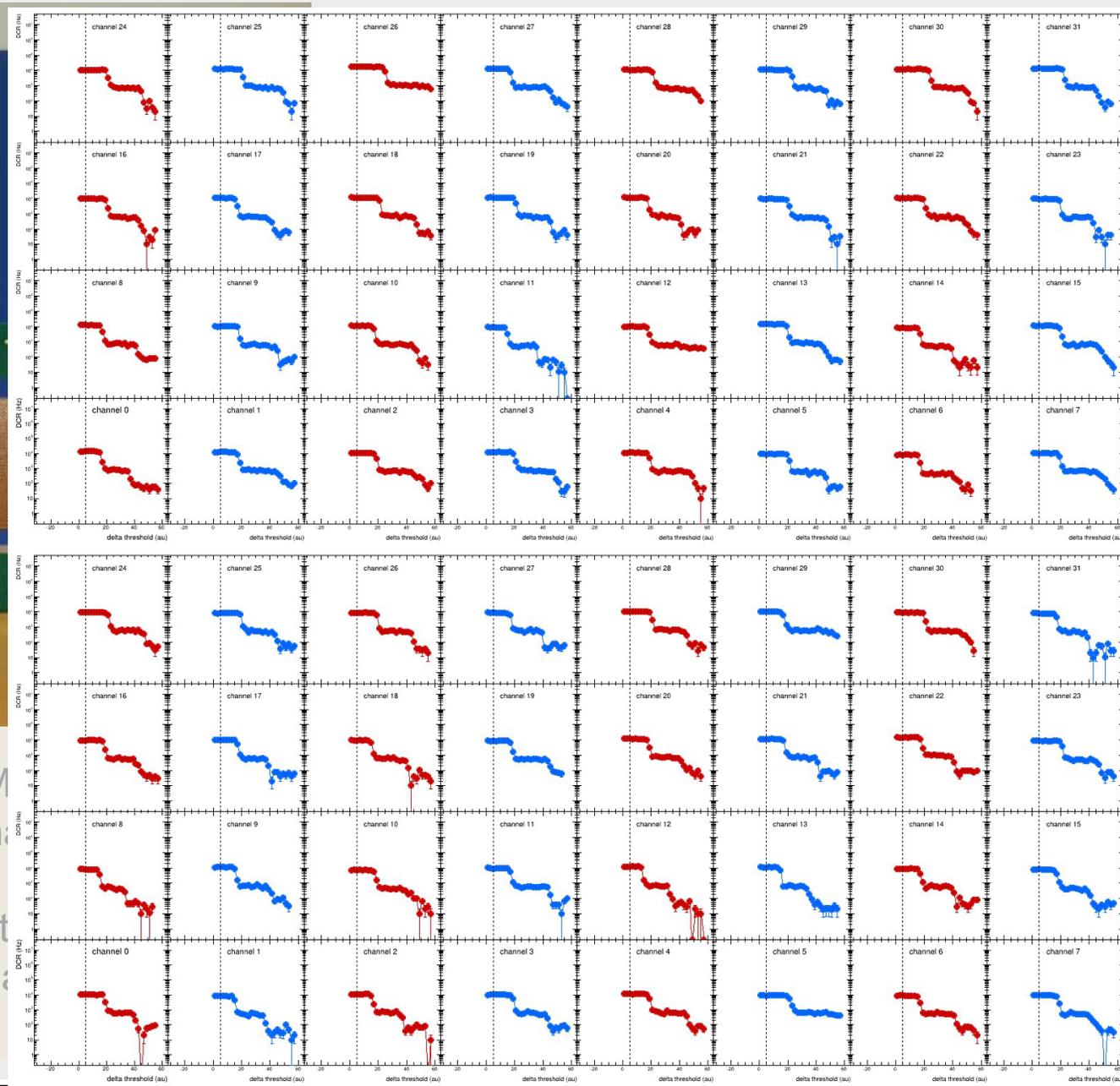
## Mounted in the last weeks

HV and signals via flex  
pcb with 1 mm bending  
radius

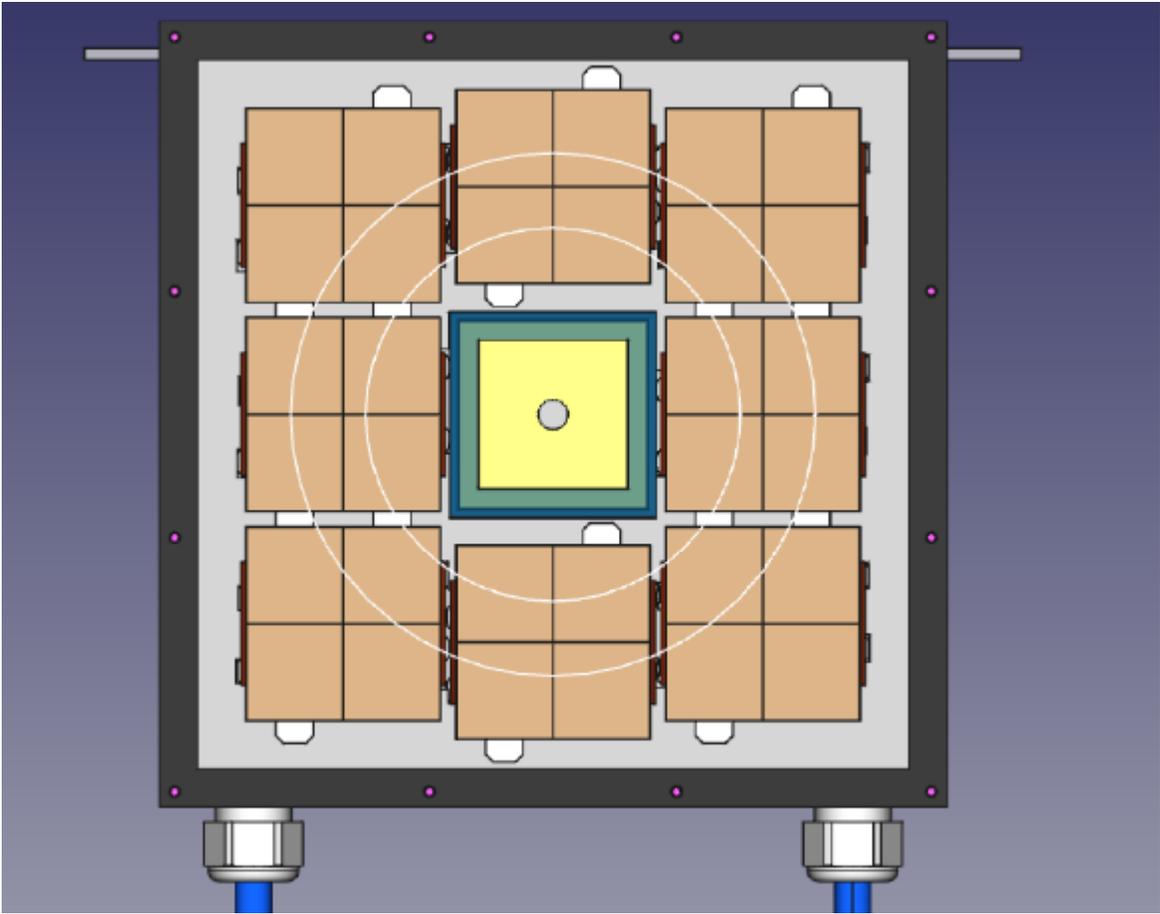
Rigid flex design to host  
HV LC-filters

Back-side temperature  
sensors

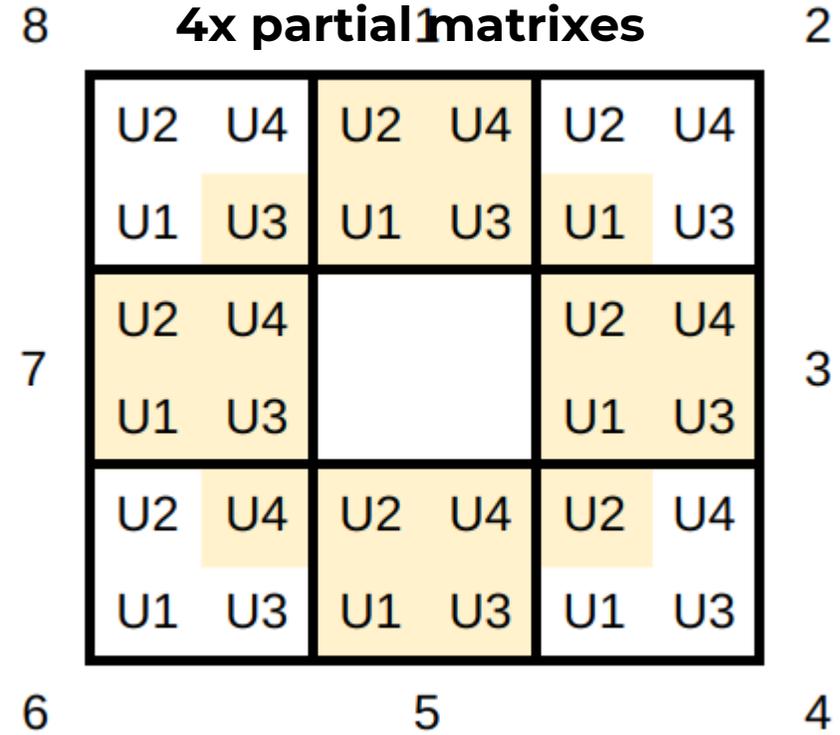
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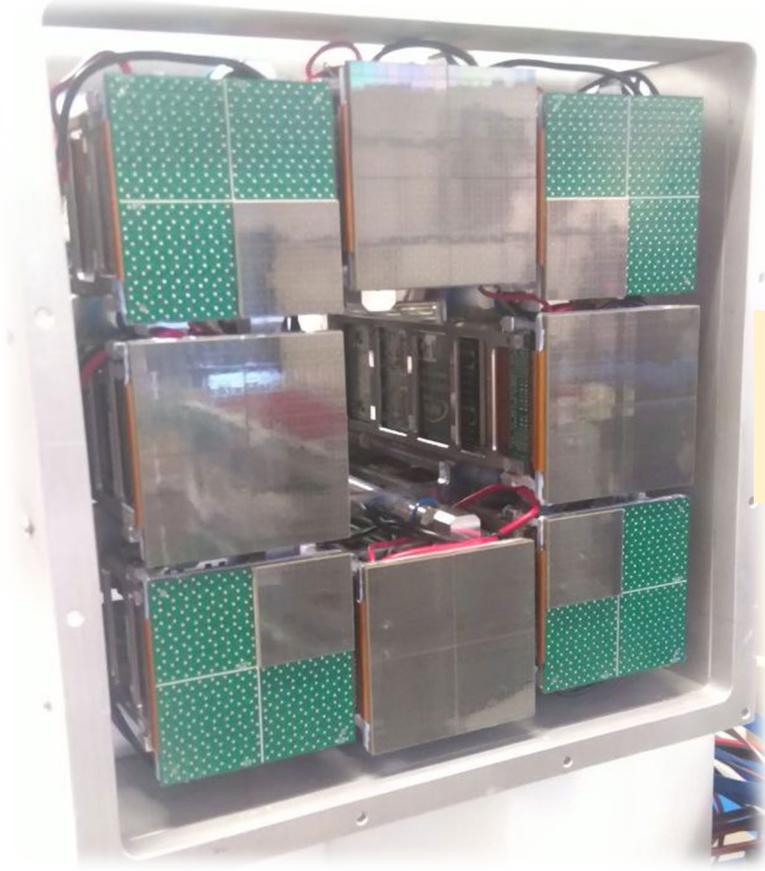
# 2023 test beam prototype at CERN-PS



**Actual SiPM layout:  
4x full matrixes  
4x partial matrixes**



# 2023 test beam prototype at CERN-PS



Full system integrated in Bologna for tests.  
**Now travelling to CERN!!**



# Conclusions

- **SiPMs are a feasible solution for the dRICH photodetection planes at EIC**
- 2 prototype of the readout system were developed and (up to be) tested in in beam operations